

24th International
Conference On VLSI Design



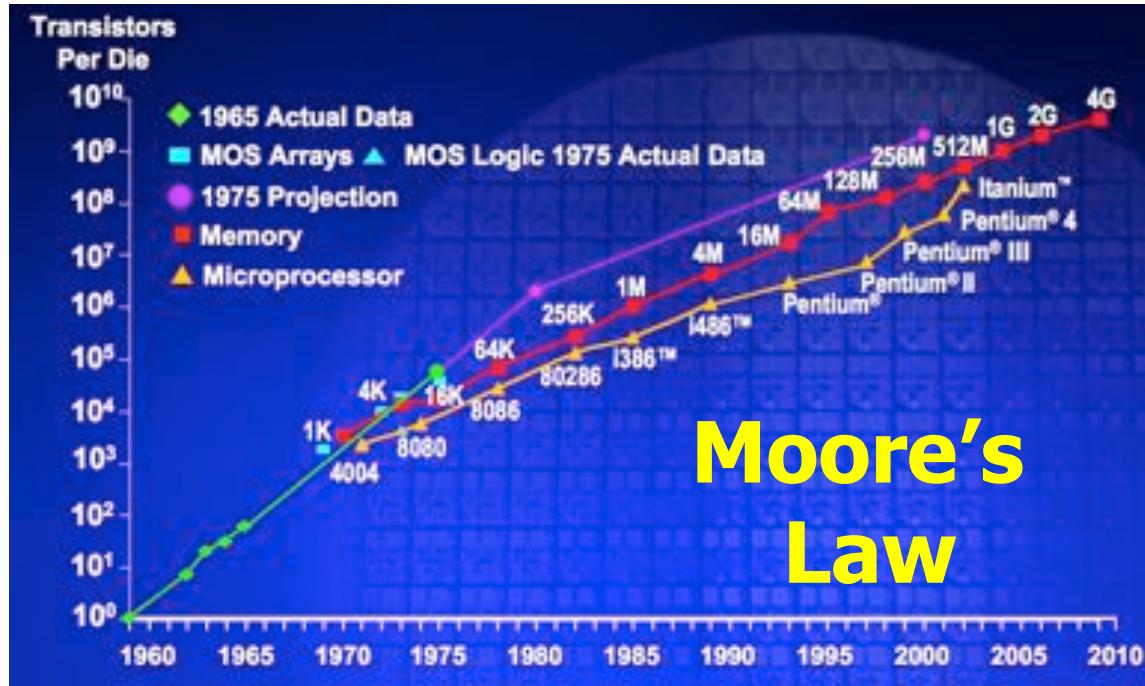
Designing Analog and RF Circuits in Nanoscale CMOS Technologies:

**Scale the Supply, Reduce the Area and
Use Digital Gates.**

Peter Kinget

Université Catholique de Louvain (Belgium)
On sabbatical from: Columbia University (New York)

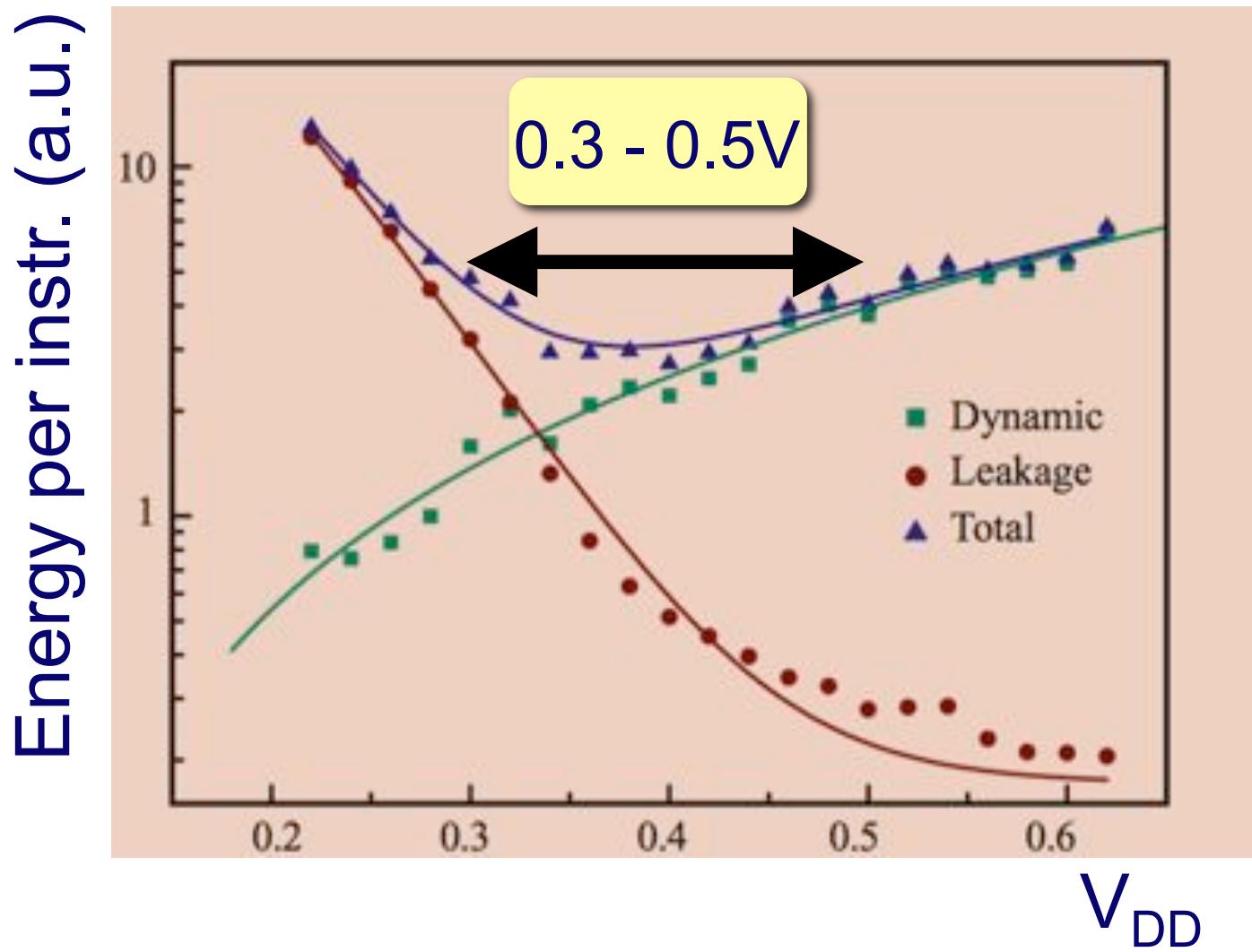
4 Decades of Exponential Growth



G. Moore, "No Exponential is forever..., but we can delay forever," ISSCC 2003

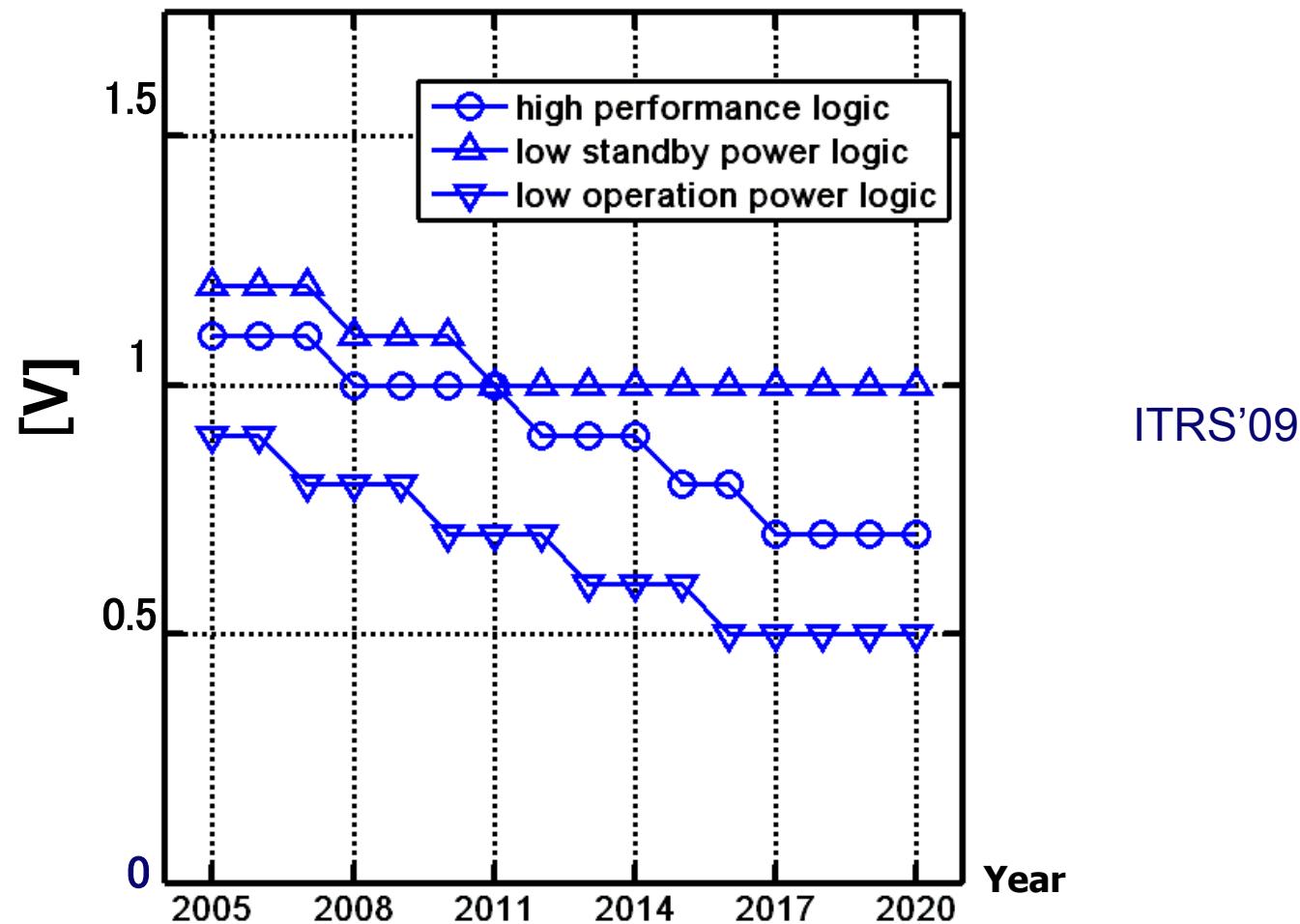
- IC Technology Progress ≡ Device Scaling
- IC Design Progress ≡ More Integration
 - Analog, RF, digital ... on a Chip = System on Chip
- Next, highly scaled technologies...

Lowest Energy Digital V_{DD}



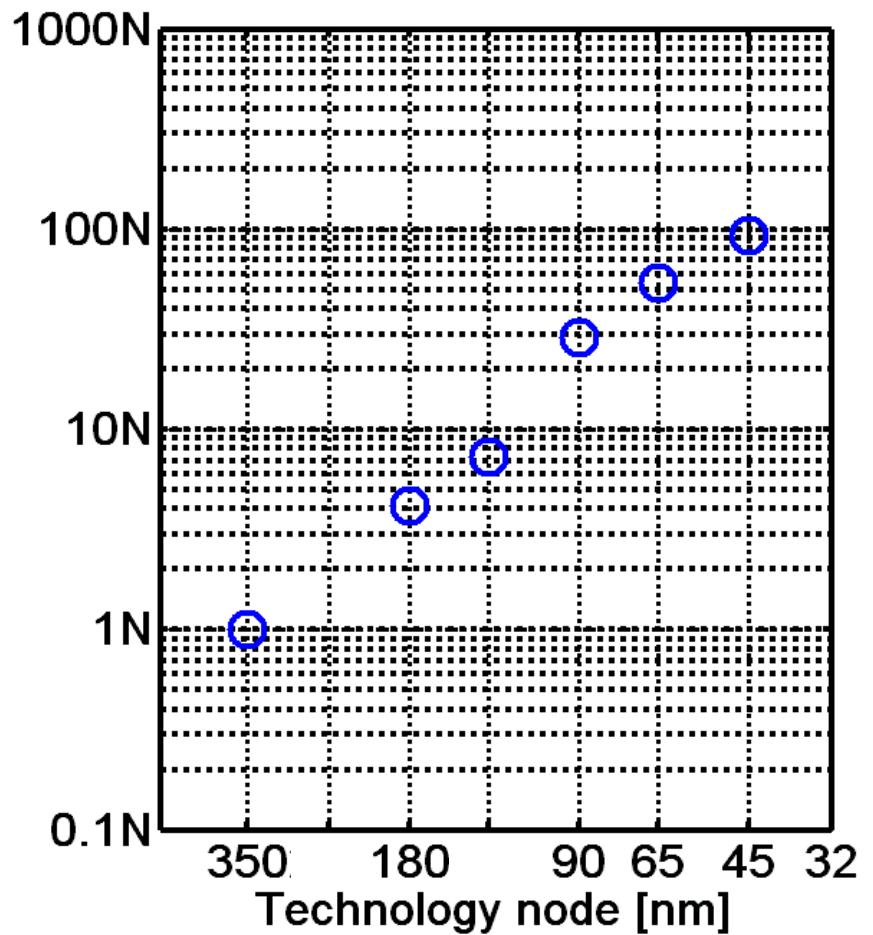
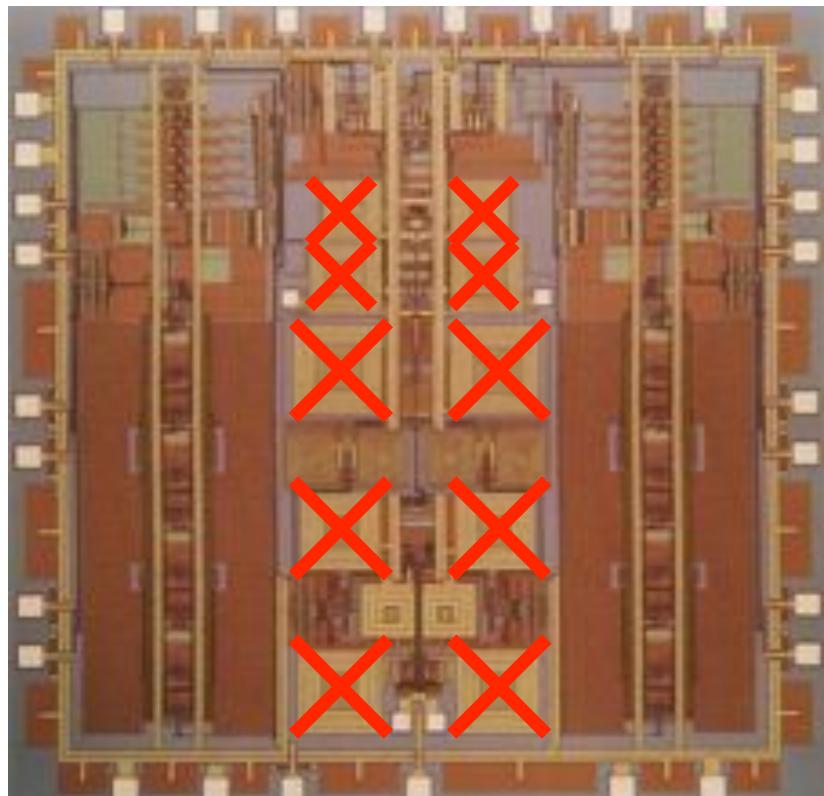
- [Hanson 2006] 8-bit microprocessor in 0.13um CMOS

V_{DD} Scaling for Nanoscale CMOS

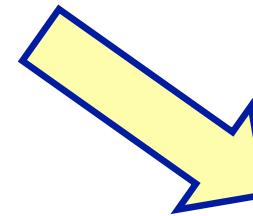
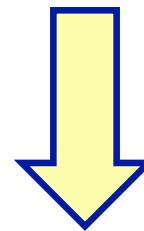
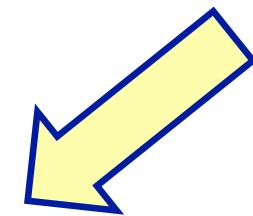


Reduce Area: Motivation

Number of DFFs within an area of 200um x 200um



Design Techniques to Keep Analog & RF Compatible with Nanoscale CMOS

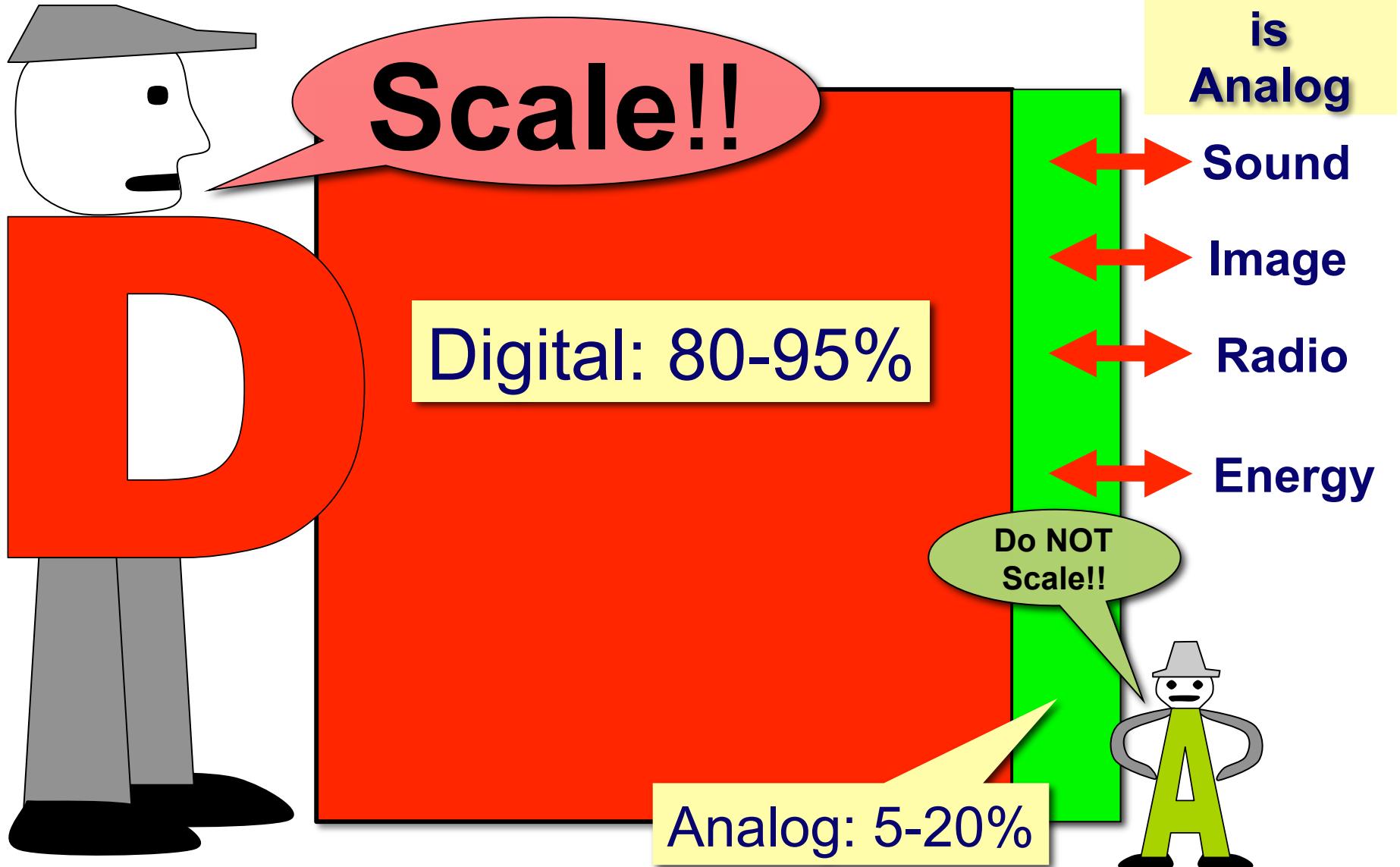


Scale the
**Supply
Voltage** of
Analog/RF
Circuits

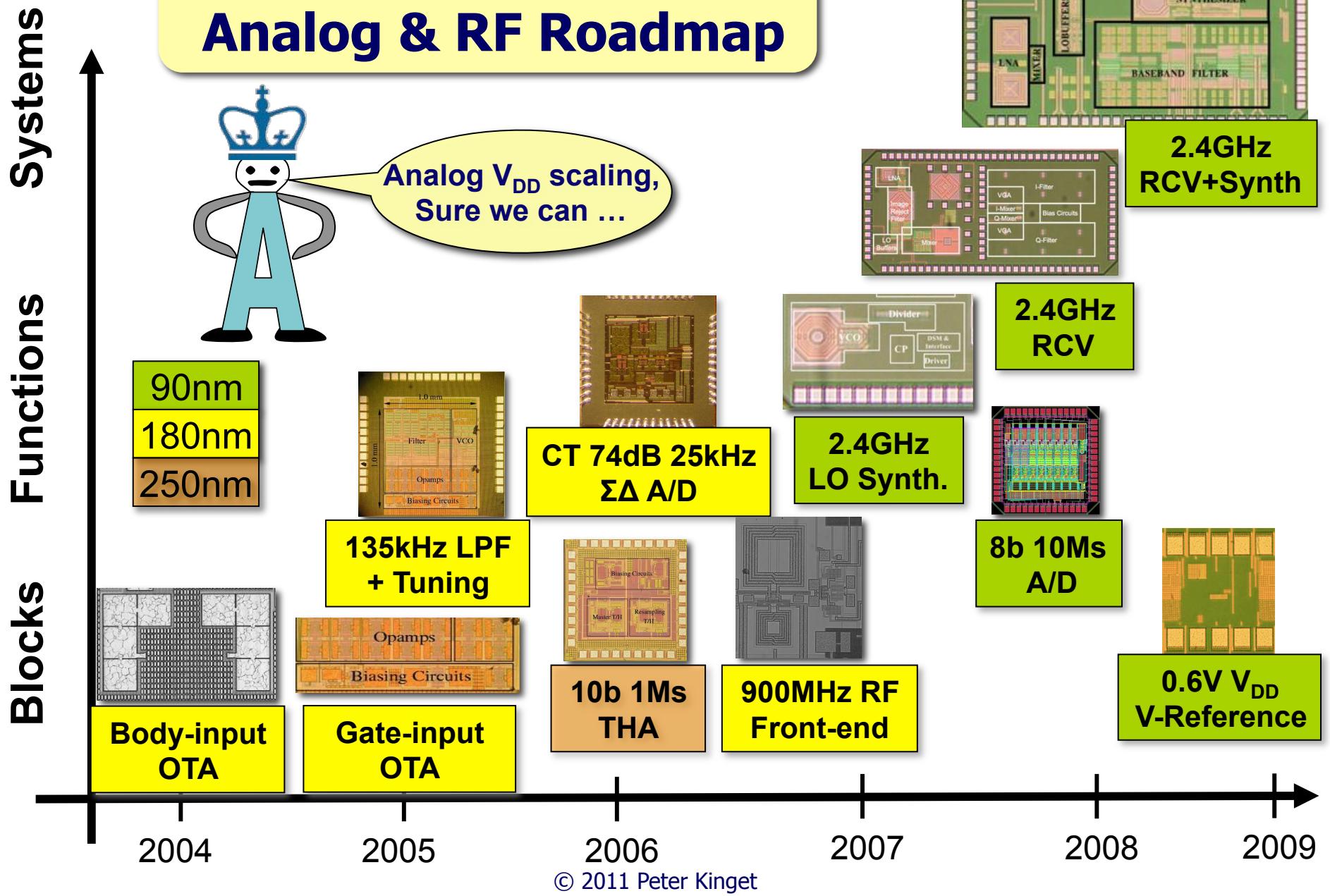
Reduce the
Area of RF
circuits

Use **Digital
Gates** to
Improve
Analog/RF
Performance

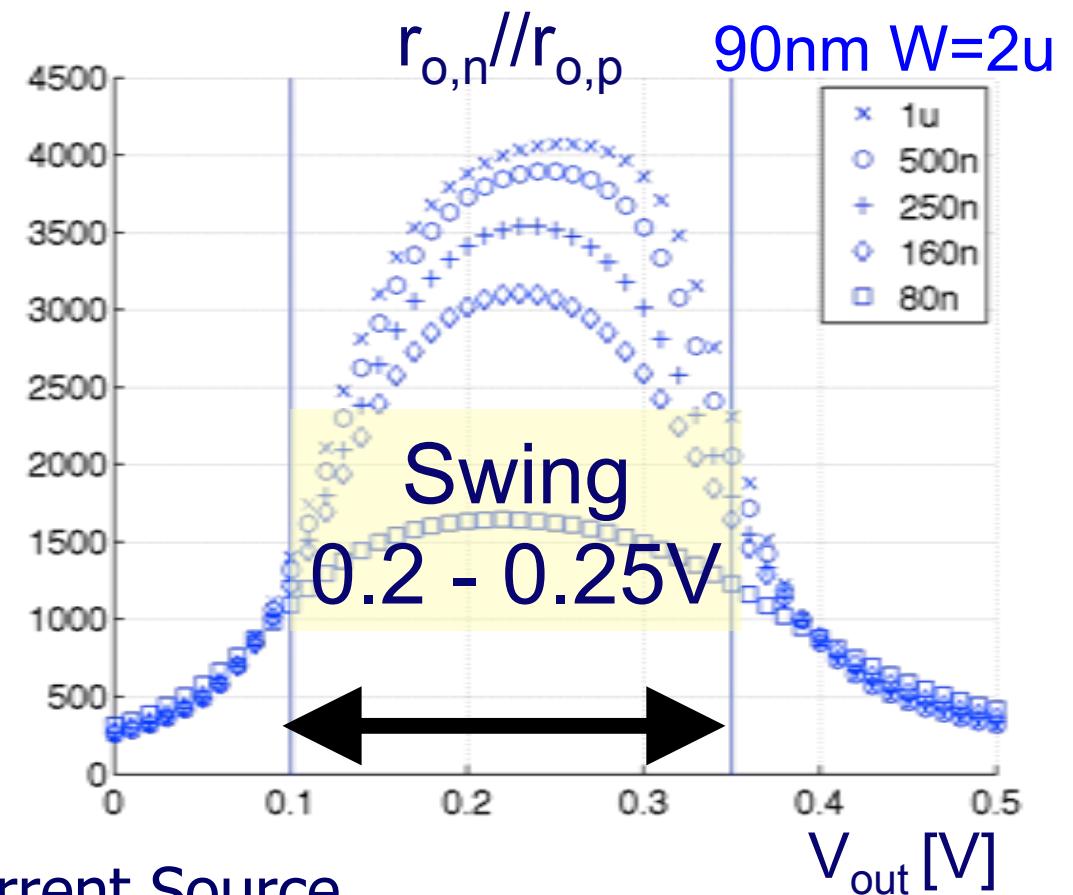
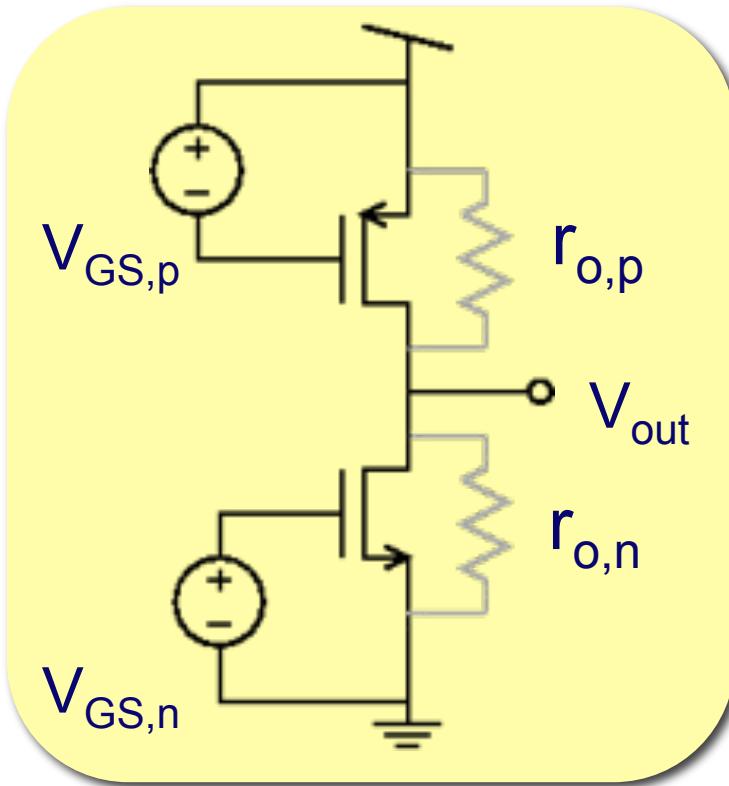
System on a Chip



Columbia's 0.5-0.6V Analog & RF Roadmap

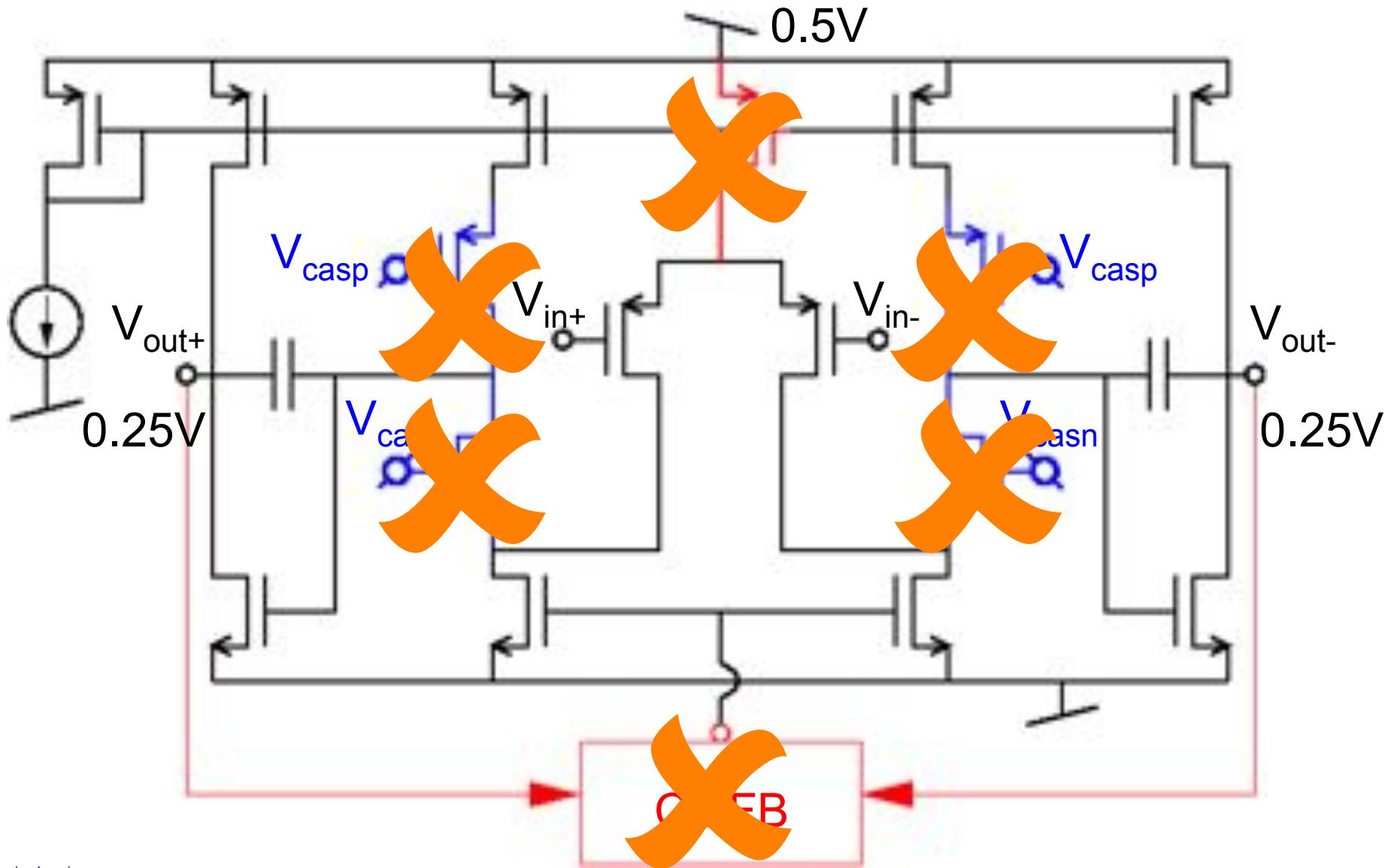


MOST Biasing: CS or VCCS



- Transconductor or Current Source
 $V_{DS} > 0.1V$ to $0.15V$ (for $V_{GS}-V_{TH} \leq 0.2V$)
- **Moderate to Strong Inversion**
 $(V_{GS}-V_{TH}) \approx 0.15V$ & $|V_{TH}| = 0.35V \rightarrow V_{GS} = 0.5V$
 $|V_{TH}| = 0.15V \rightarrow V_{GS} = 0.3V$

Ultra-LV Challenges in OTAs



simple anim.

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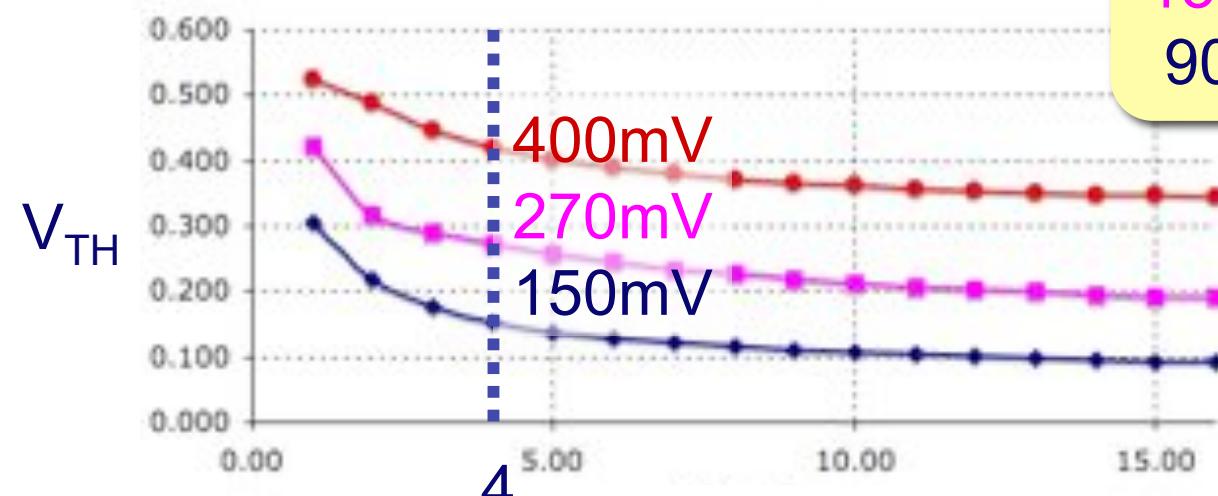
Ultra-low Voltage Analog & RF Design

- Exploit full device characteristics
 - RSCE, Body-bias
- Rethink your circuit topologies
 - Eliminate stacks, LCMFB, CMFF, Neg. G
 - Address leakage (cascaded switches),
 - MOS or Schottky based references
- Revise your architectures
 - Eliminate switches in signal path (e.g., RTO),
 - RF front end: Current mode operation/interfaces
 - RF Baseband: Optimize structure
- True low voltage design: no voltage boosting, no special devices

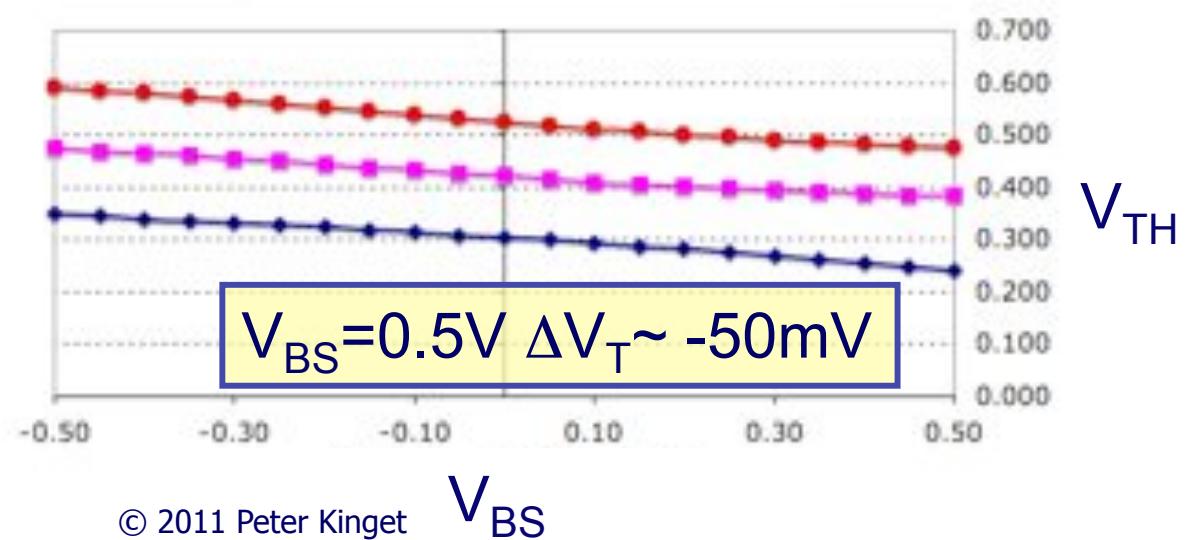
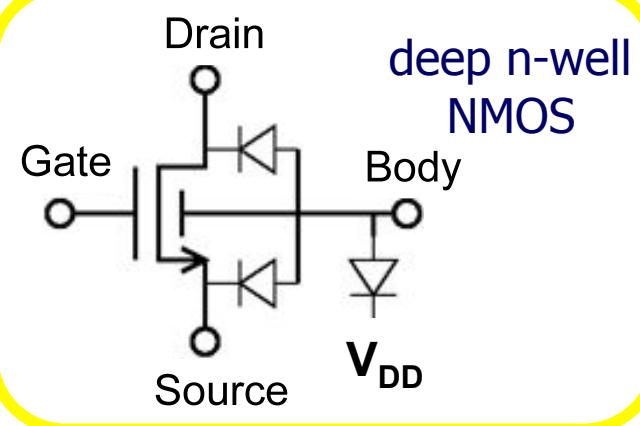
Device Level Solutions

- RSCE

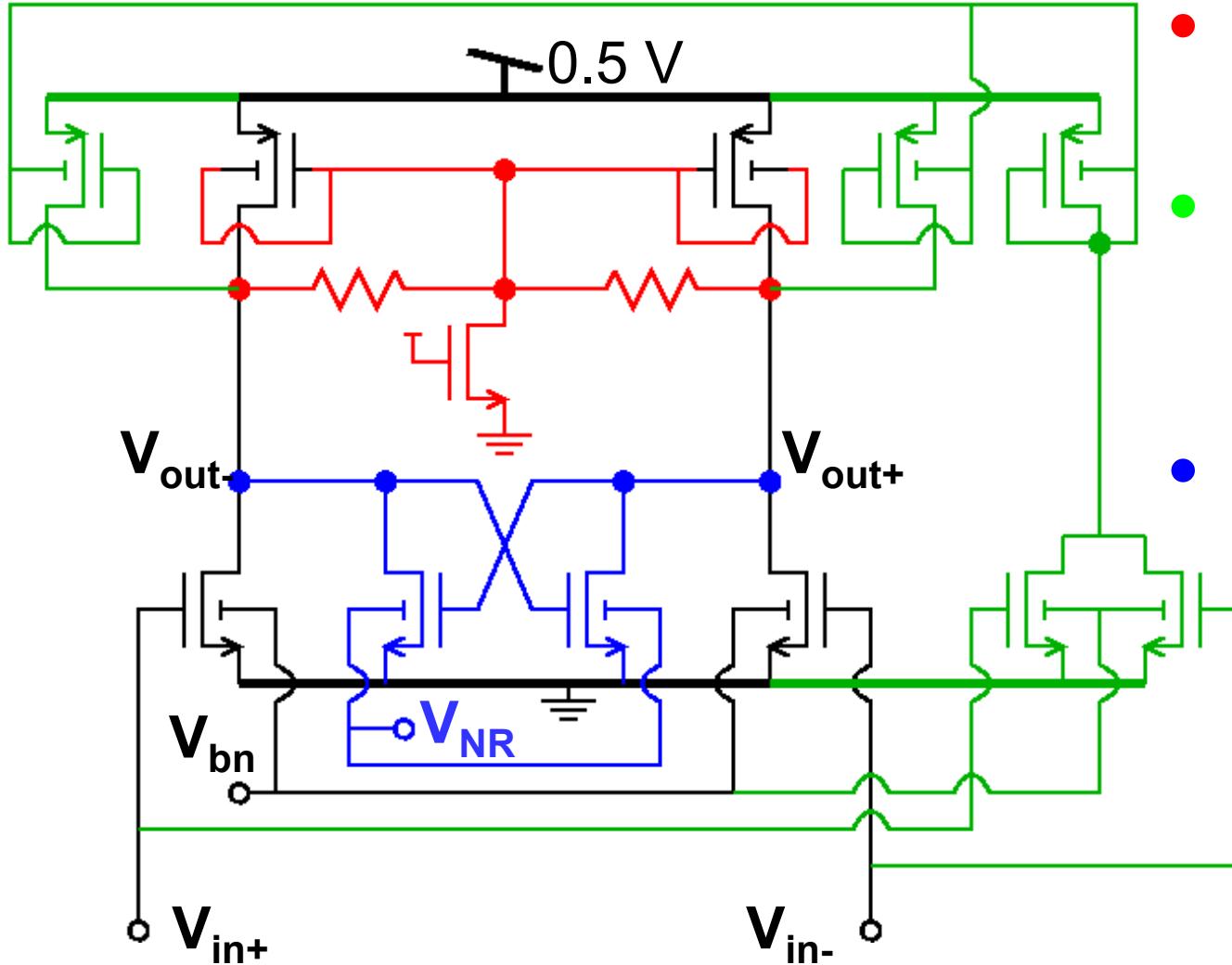
$V_T \downarrow$ as $L \uparrow$



- Forward Body-Bias

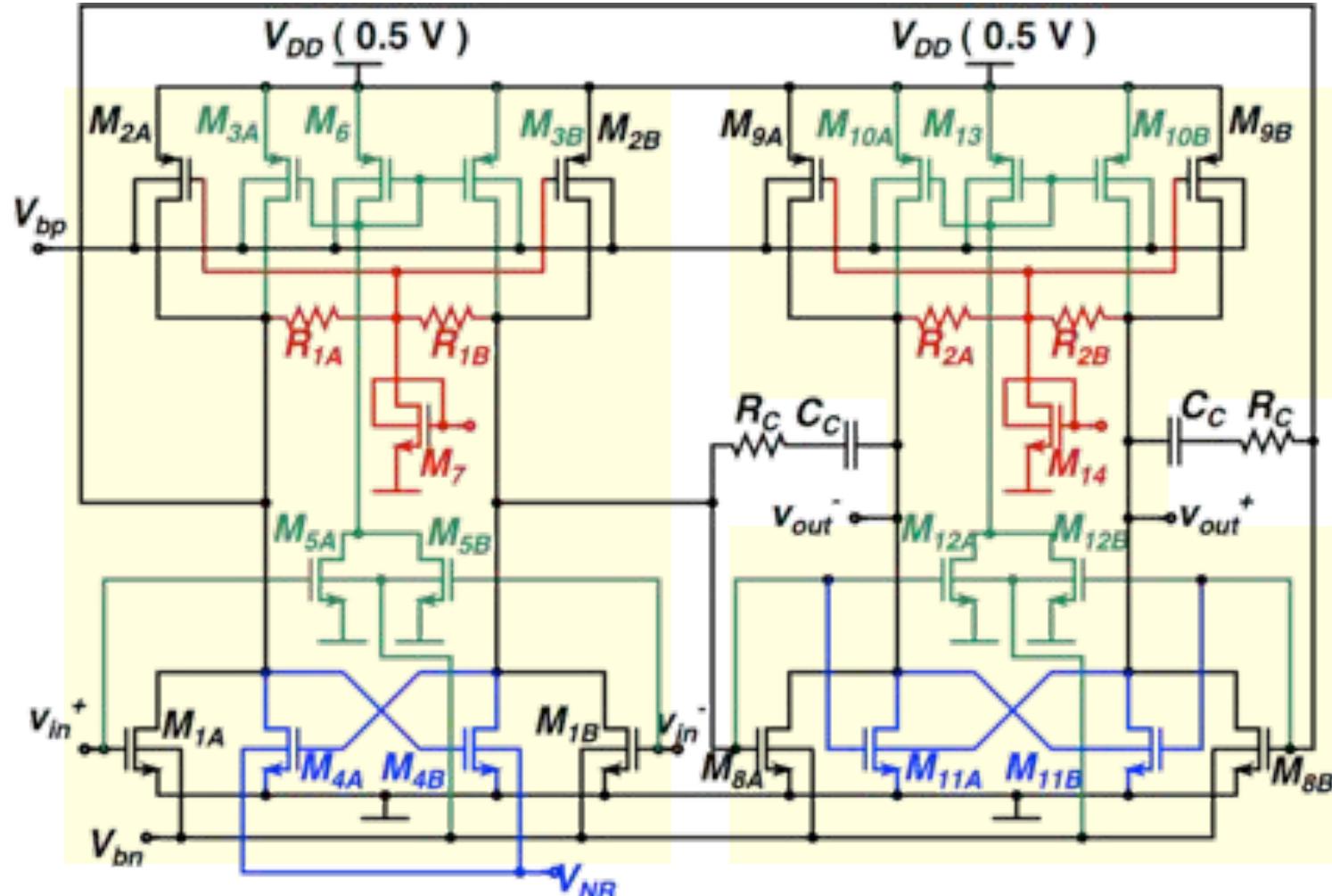


0.5V Gate-Input OTA Stage



- Local Common-Mode Feedback
- Common-Mode Feed Forward Cancellation
- Neg. G Gain Boost

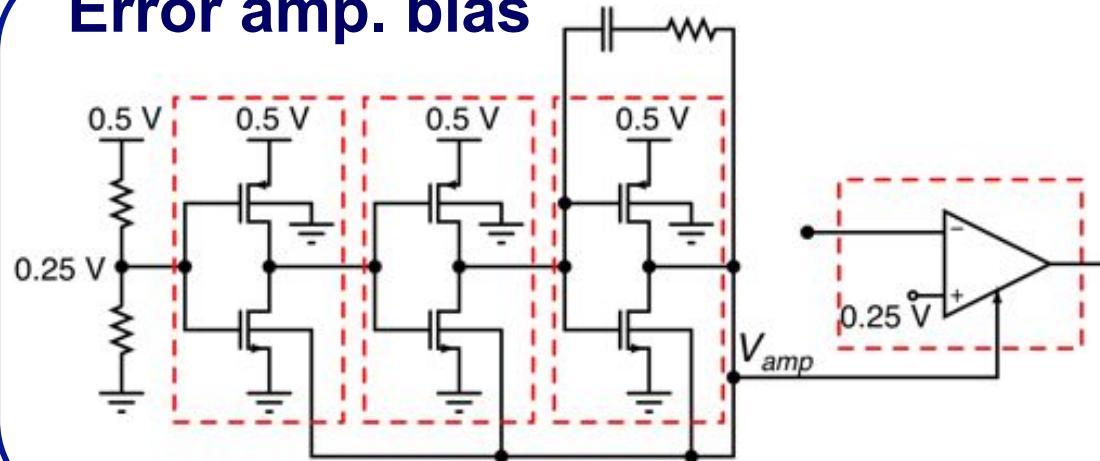
0.5V Two-Stage OTA



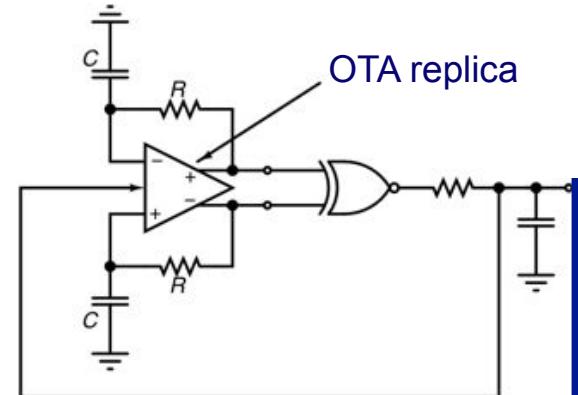
- $V_{T,nom} = 0.5V$; CM_{in} 0.4V, 0.18um CMOS
 - 62dB DC gain; 10MHz GBW; 10pF C_{L,diff}; 75uW

On-Chip Biasing Circuits

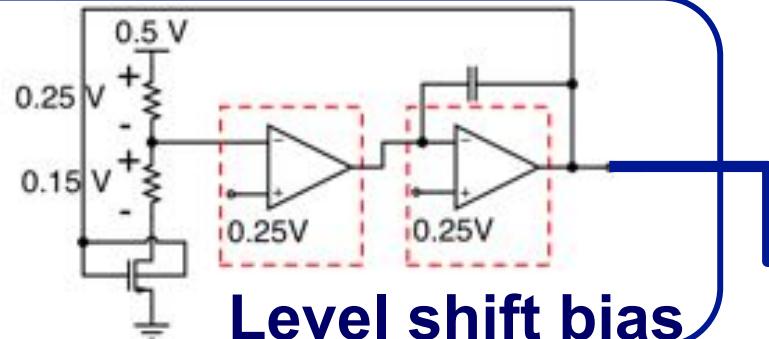
Error amp. bias



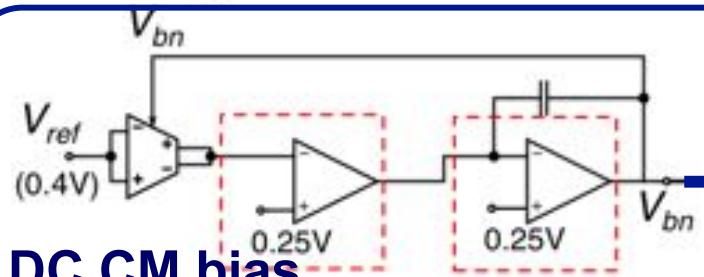
Gain bias



OTA (one stage)



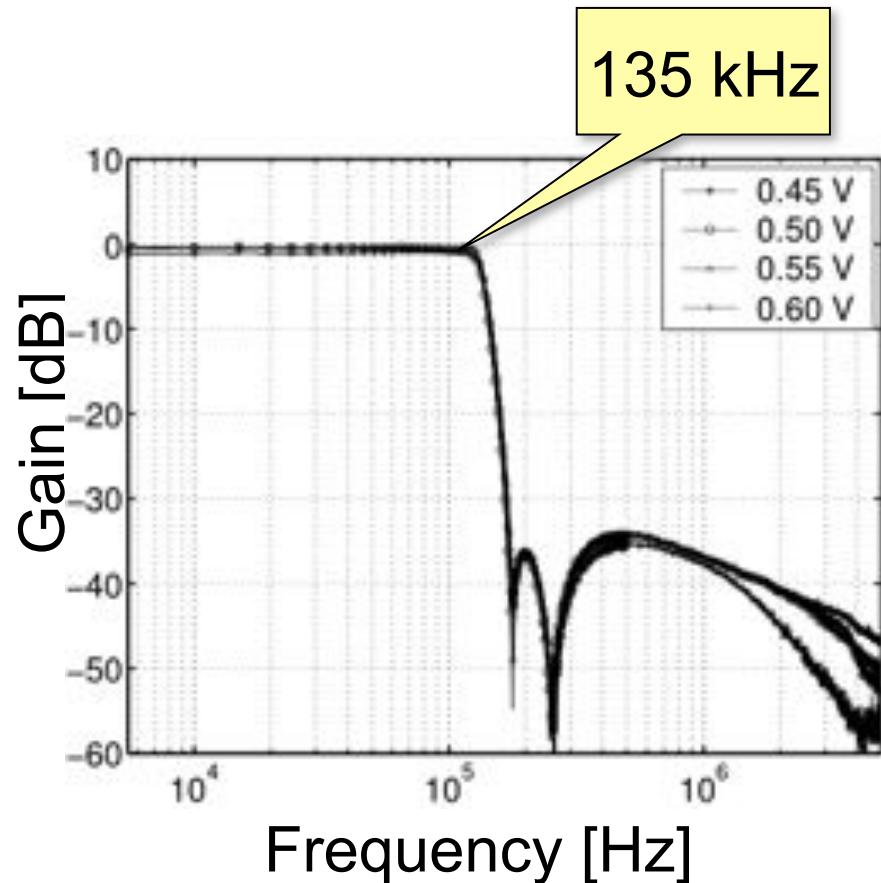
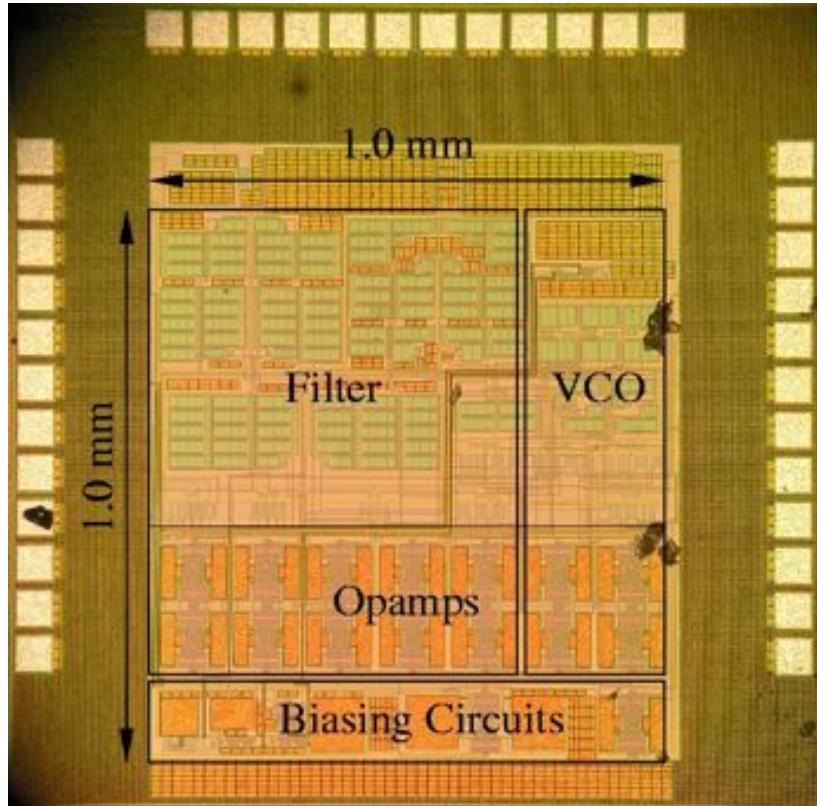
Level shift bias



DC CM bias

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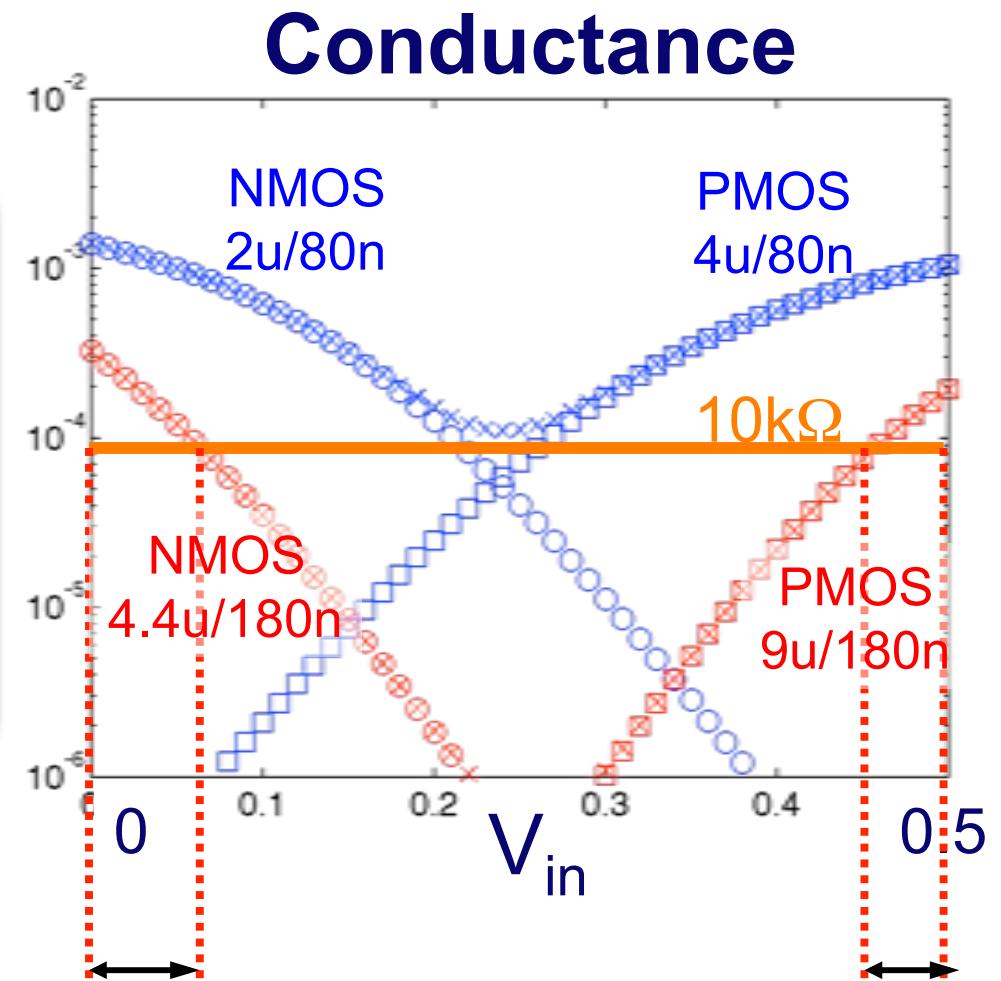
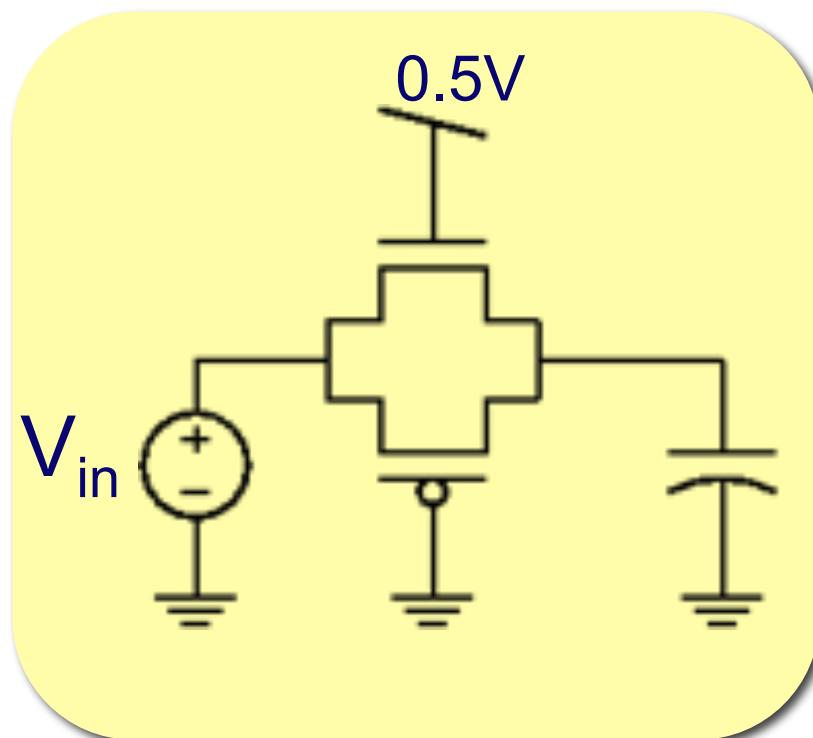
0.5V Fully Integrated 5th Order LPF



- Operation at 0.45 V to 0.6 V
- 1.1 mW power dissipation
- 57 dB dynamic range

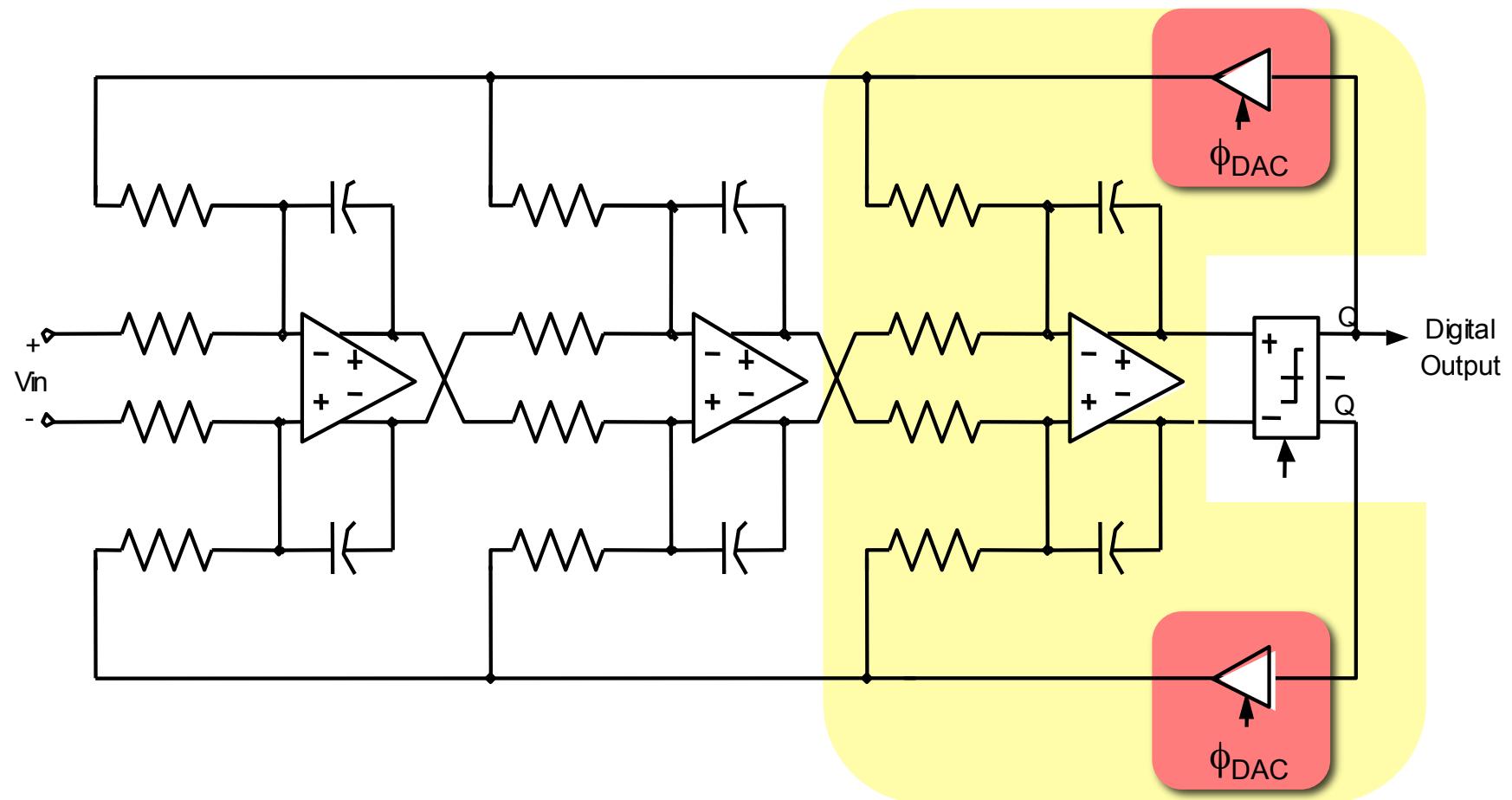
[Chatterjee, Tsividis, Kinget,
ISSCC05, JSSC05]

Floating Switch Challenge

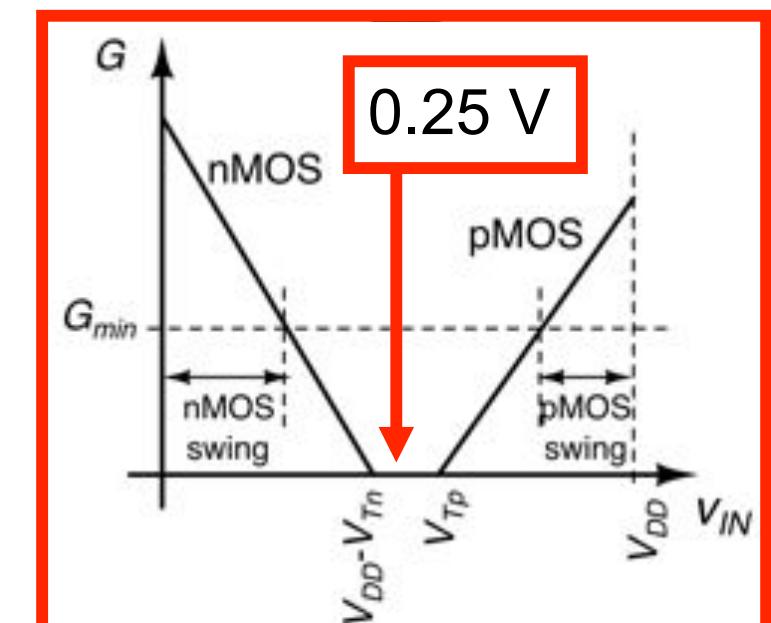
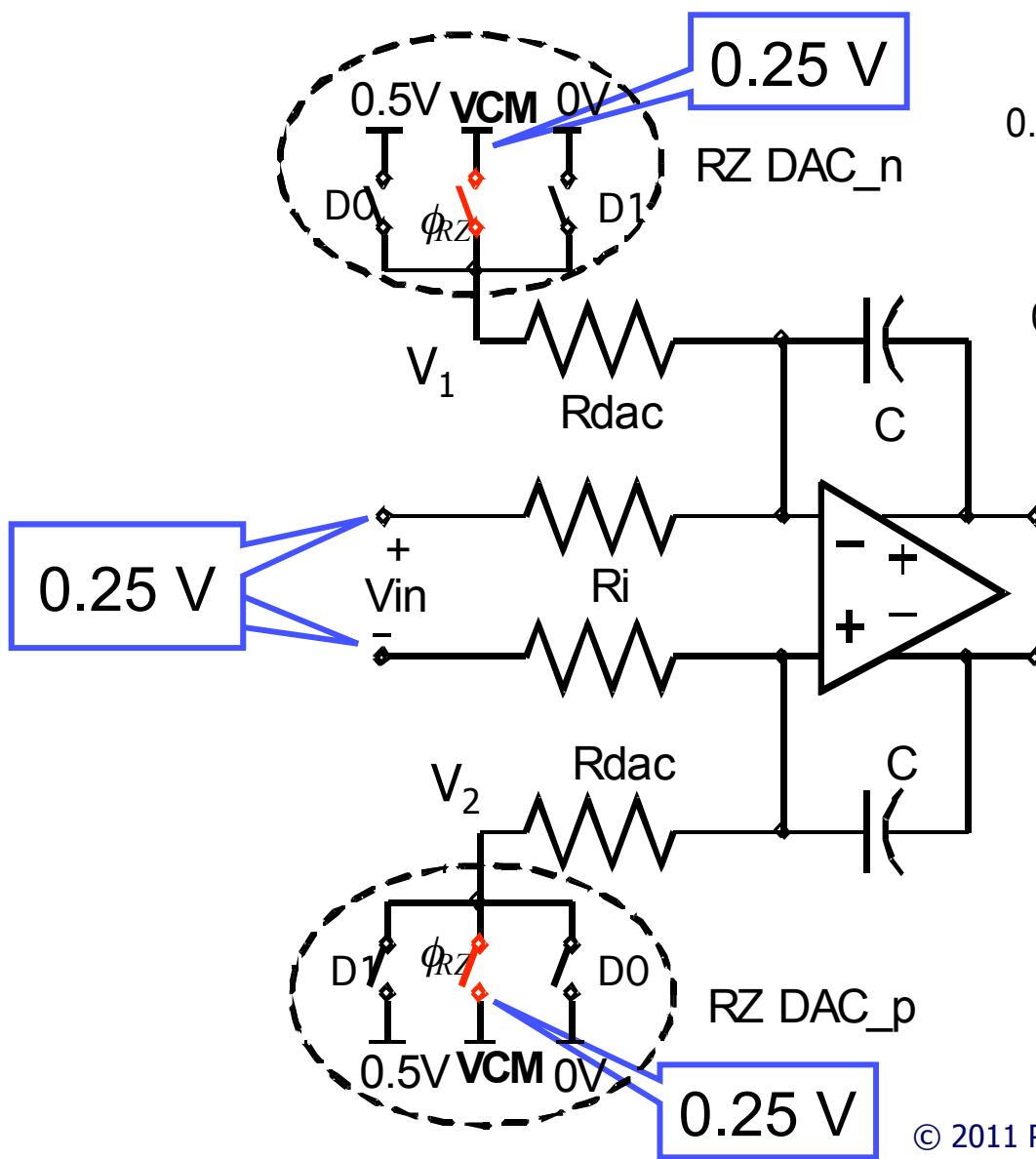


3rd order CT $\Sigma\Delta$ Modulator

Using Active RC integrators



RZ Challenge: Switches at $V_{DD}/2$



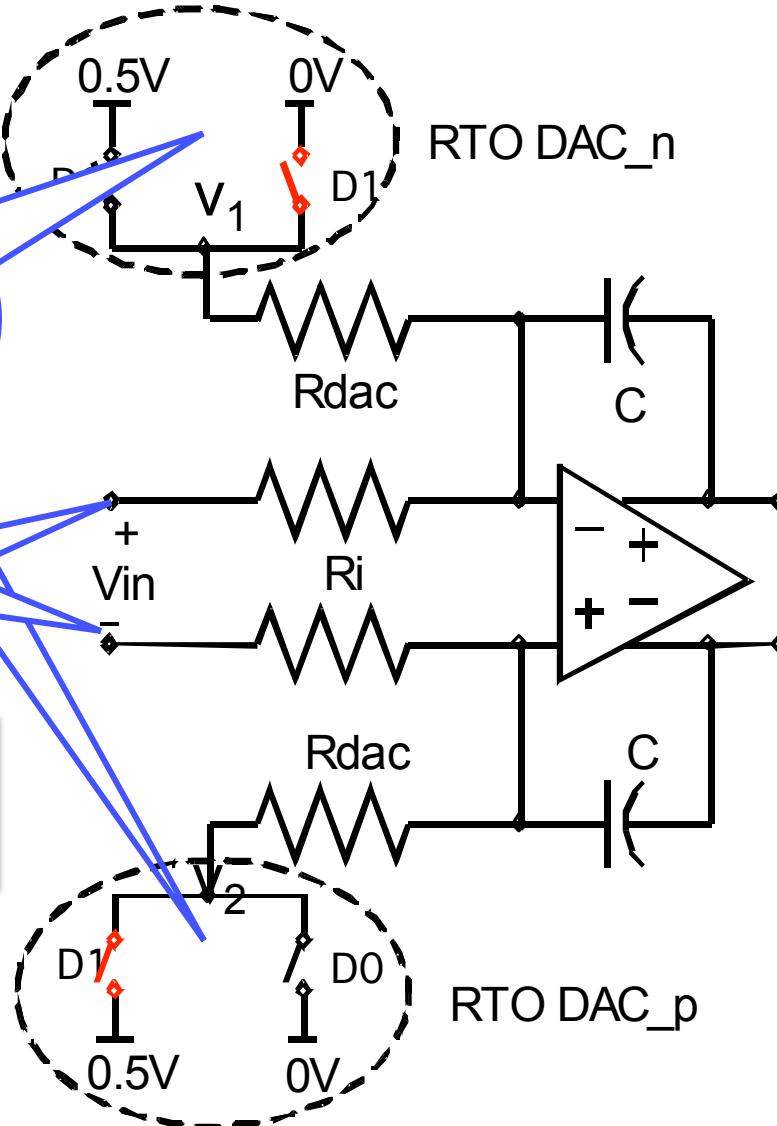
Solution: Return-to-Open

When RZ:
(Q=1)

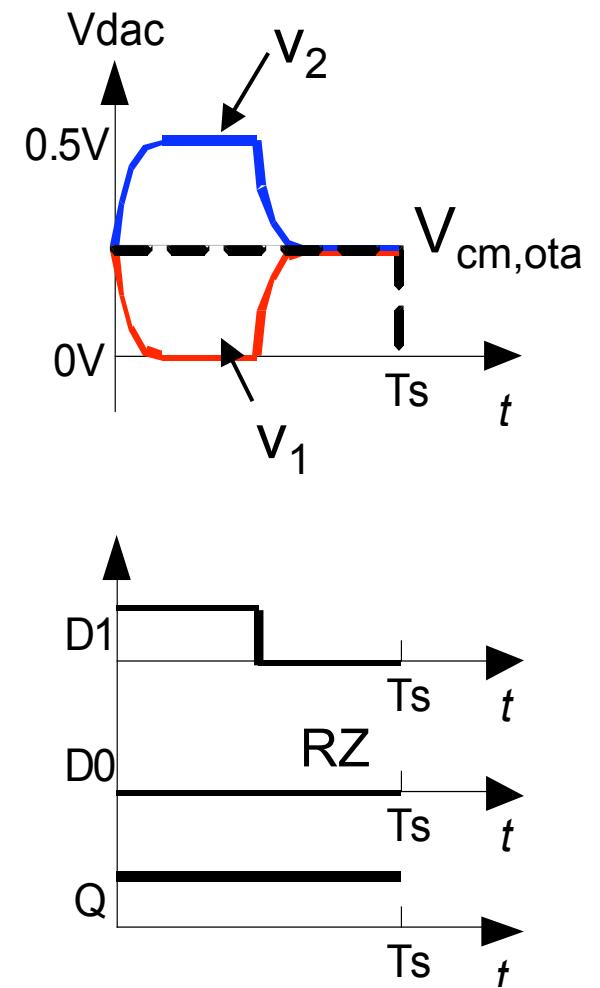
Problem
switches removed

0.25 V

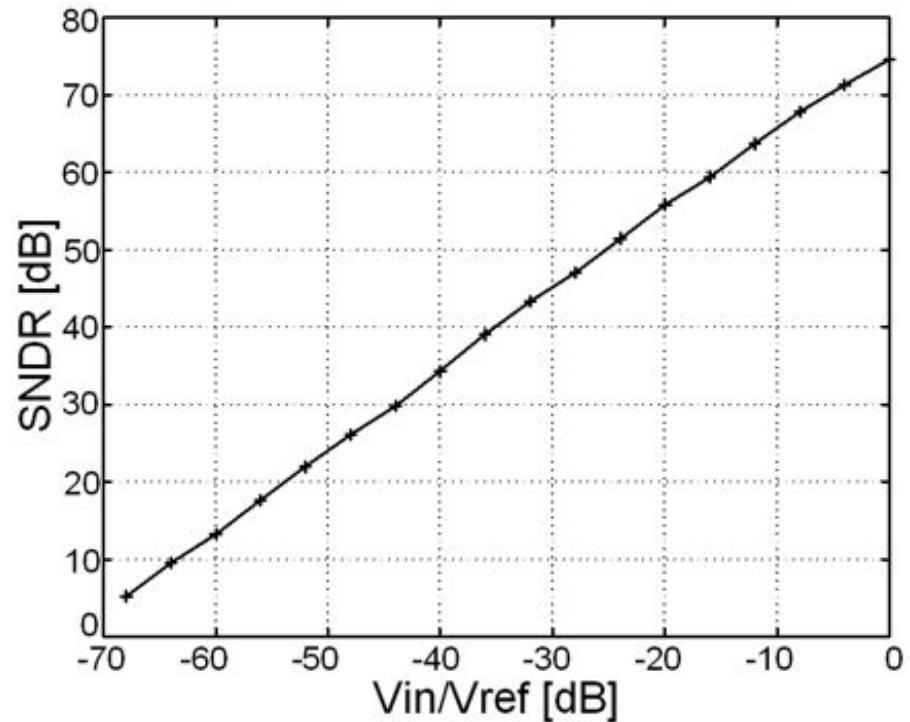
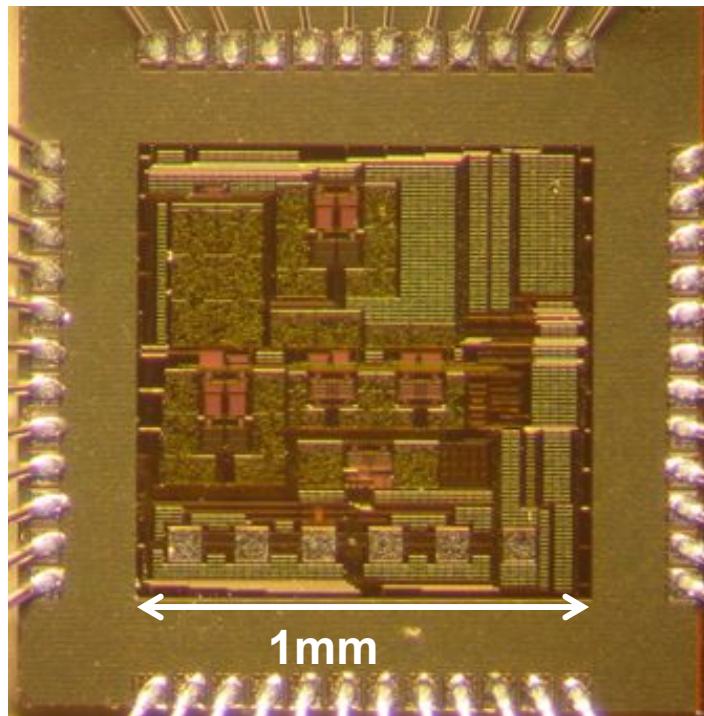
☺ Lower
Noise



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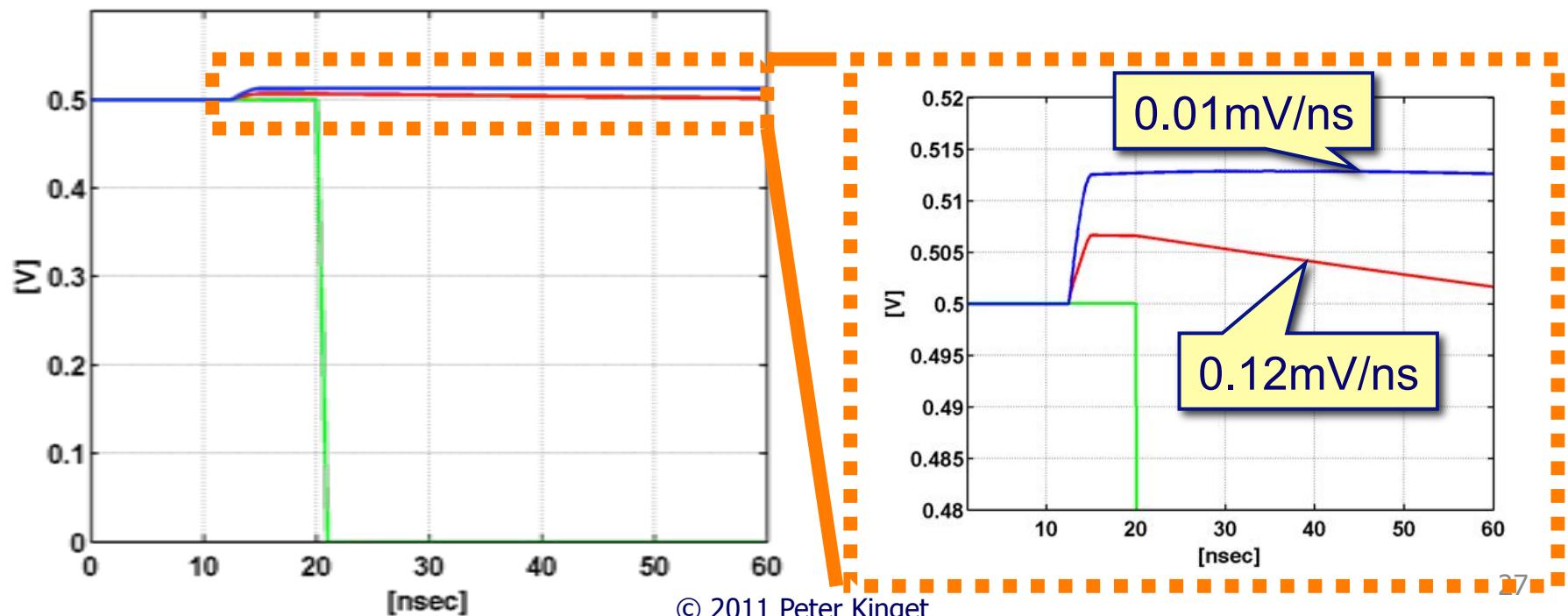
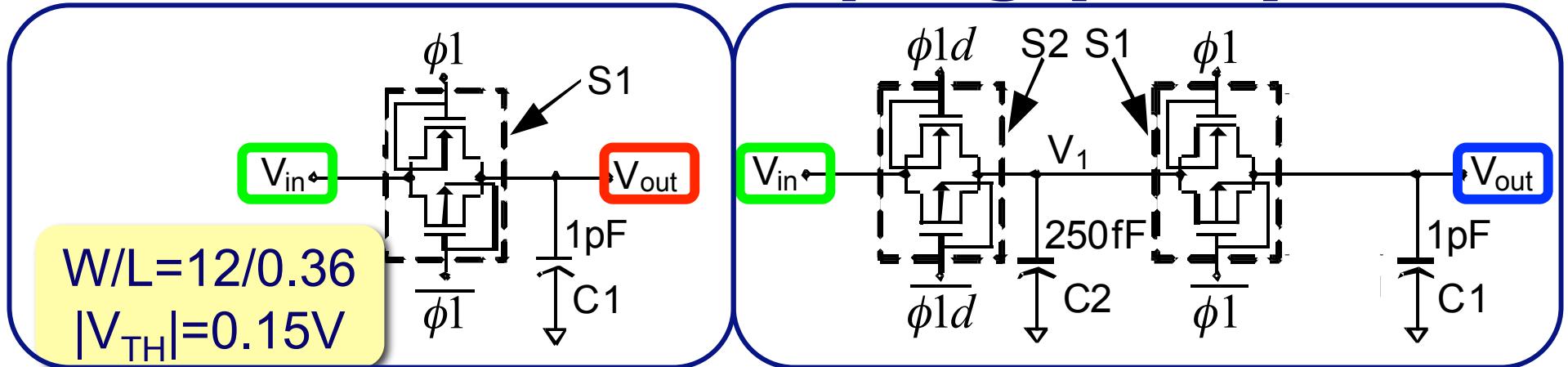


0.5V 74 dB SNDR 25kHz $\Sigma\Delta$ Modulator

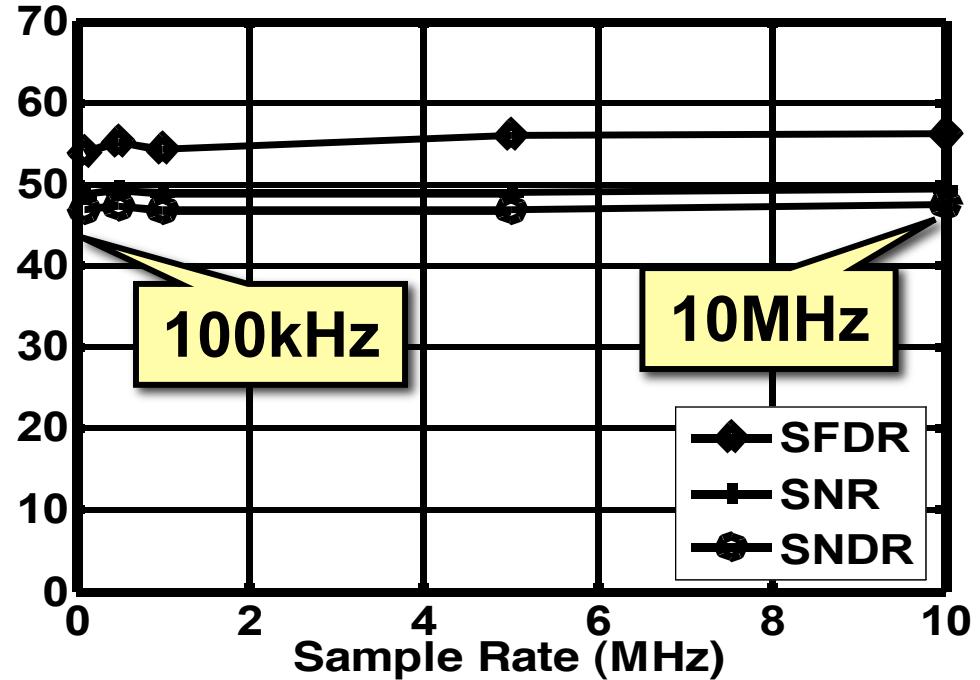
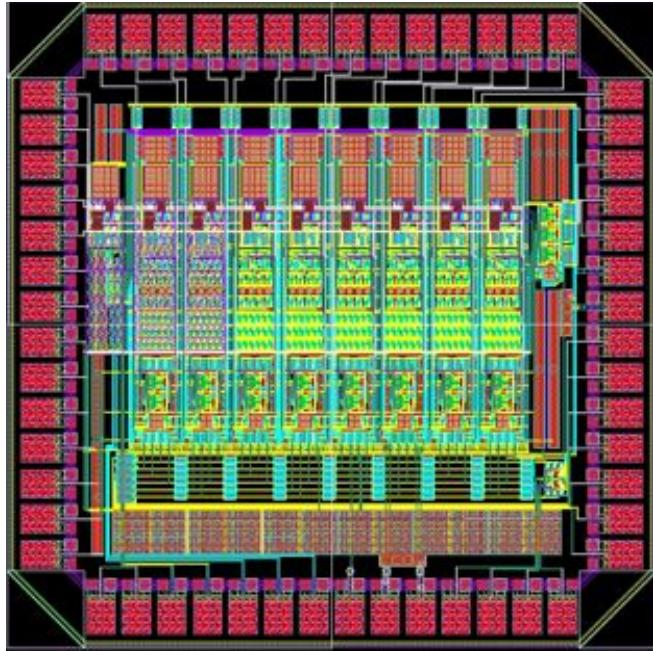


- Operation for $V_{DD} = 0.45V$ to $0.8V$
- Return-to-open architecture, body-input gate-clocked circuits
- 74dB SNDR, 25kHz, 64x OSR, $300\mu W$, $0.18\mu m$ CMOS
- [Pun, Chatterjee, Kinget, ISSCC 06, JSSC 07]

'Low V_{TH} ' switch leakage: Cascaded Sampling (Sim.)



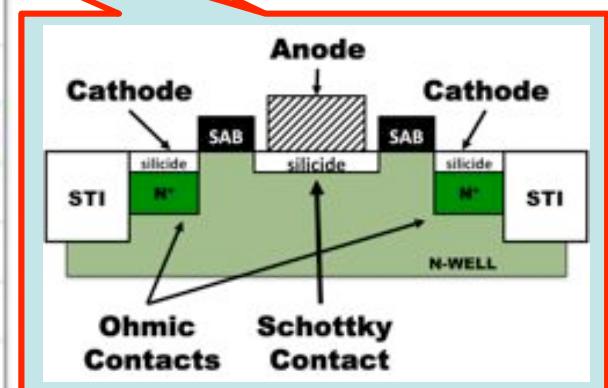
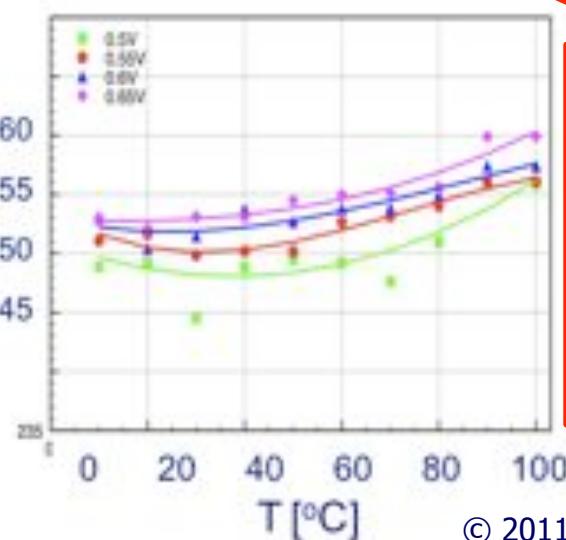
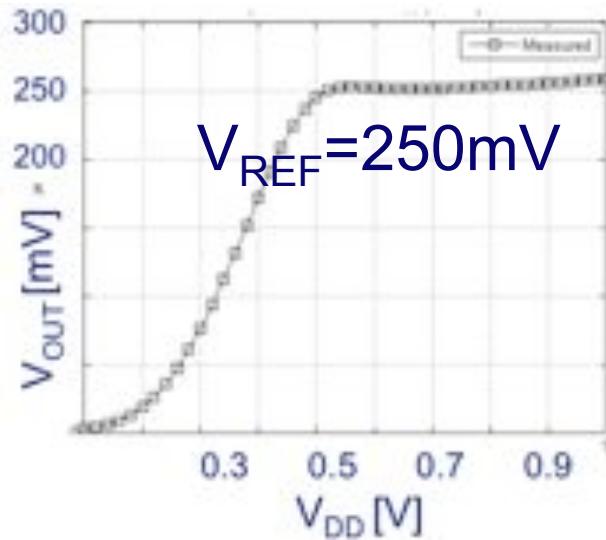
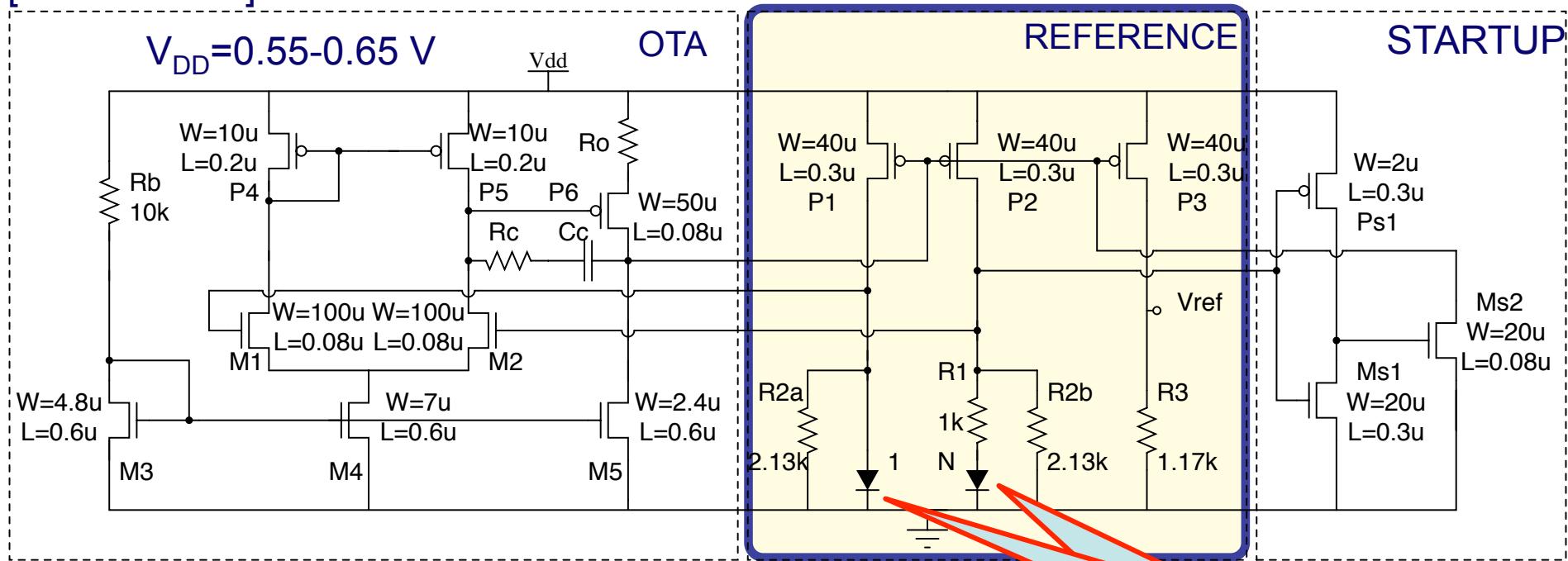
0.5V 8bit 10Msps Pipelined ADC



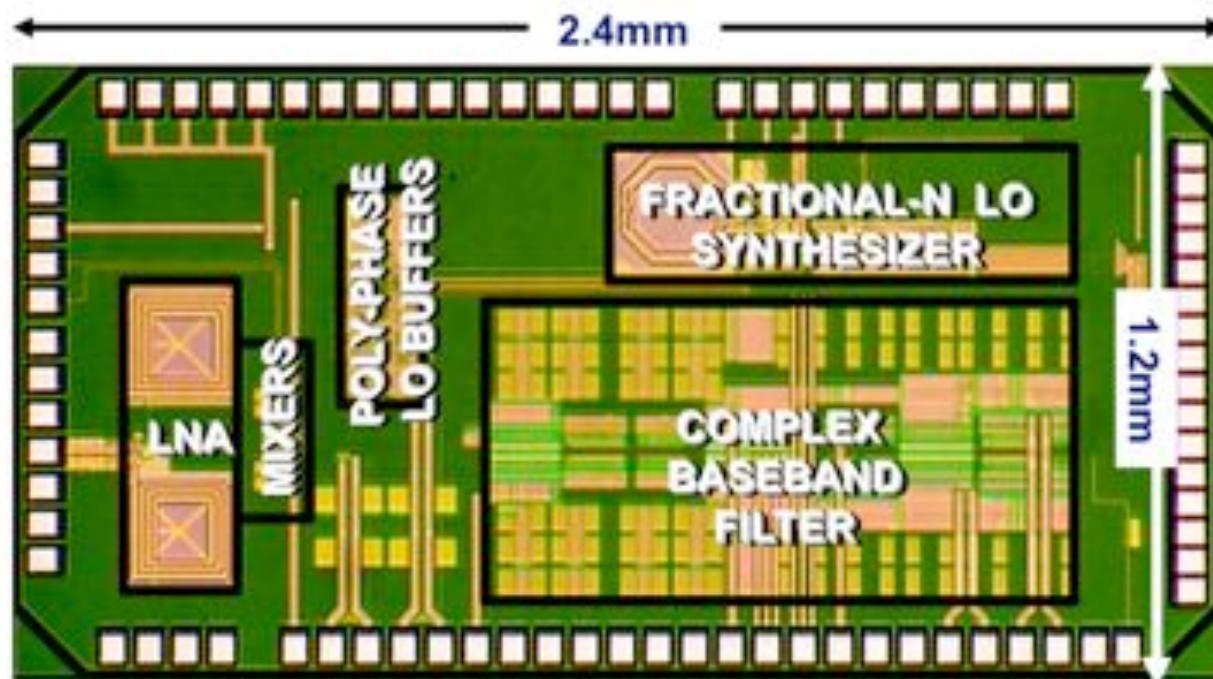
- No internal voltage or clock boosting; regular devices; cascaded sampling technique.
- Aux. S/H for the sub-ADC to eliminate front-end SHA.
- 10Msps: SNDR 48dB@101kHz, 43.3dB@4.9MHz.
- 2.4mW in 90nm CMOS [Shen, Kinget, VLSI07, JSSC08].

ULV Schottky Reference

[90nm CMOS]

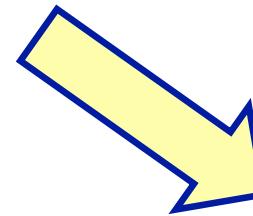
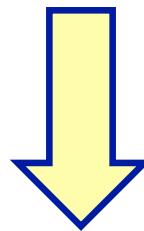
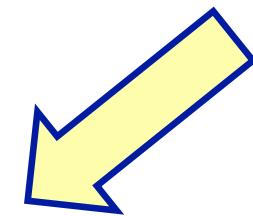


0.6V 2.4GHz ZIF/LIF RCV + Synth.



- 2.9 mm² - 90nm RVT CMOS - 64-pin QFN package
- 2.4-2.5 GHz operation @ 0.6V & 32mW
 - 16dB NF, -10.5dBm IIP₃, 67dB Gain
 - PN -127dBc/Hz @ 3MHz offset
- Fully functional 0.55V to 0.65V V_{DD}

Design Techniques to Keep Analog & RF Compatible with Nanoscale CMOS



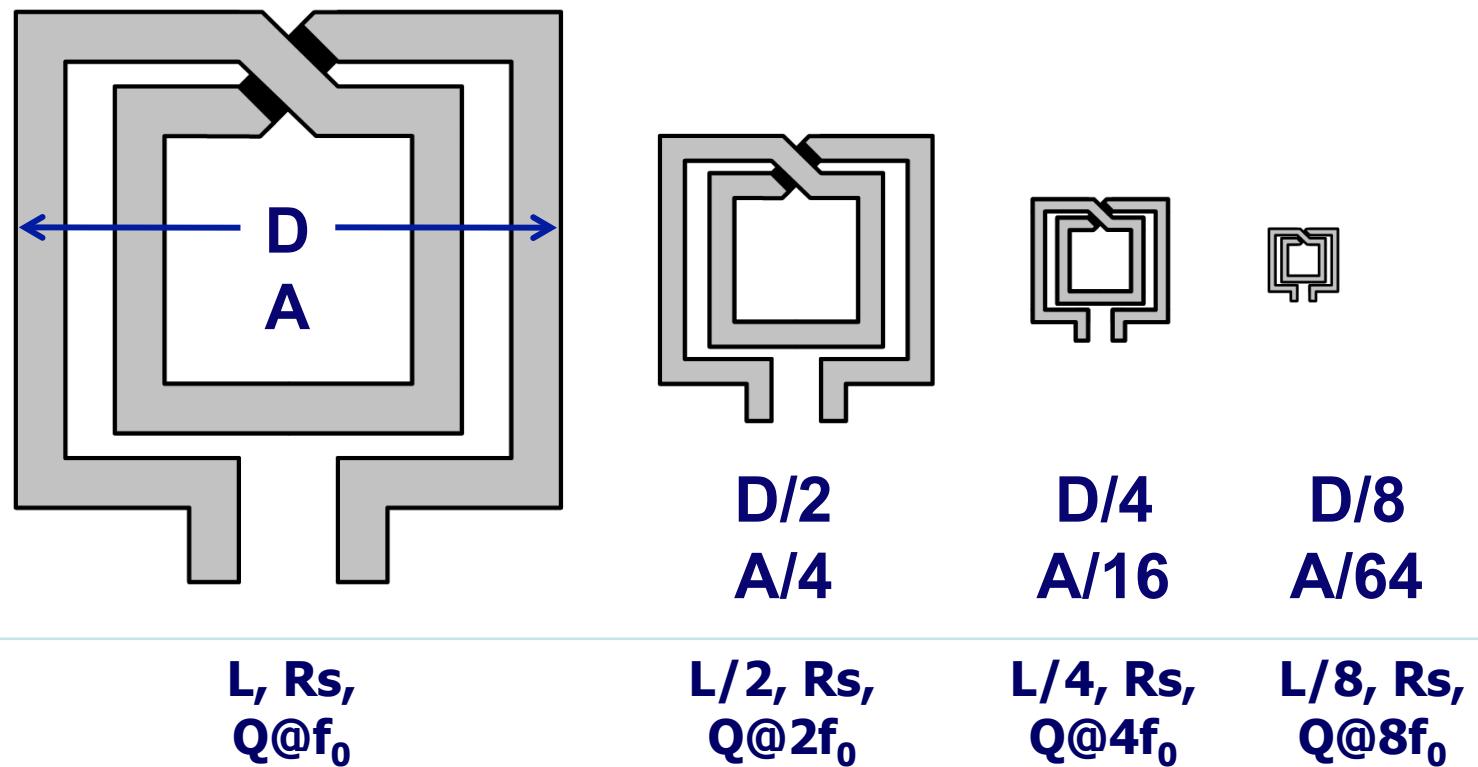
Scale the
**Supply
Voltage** of
Analog/RF
Circuits

Reduce the
Area of RF
circuits

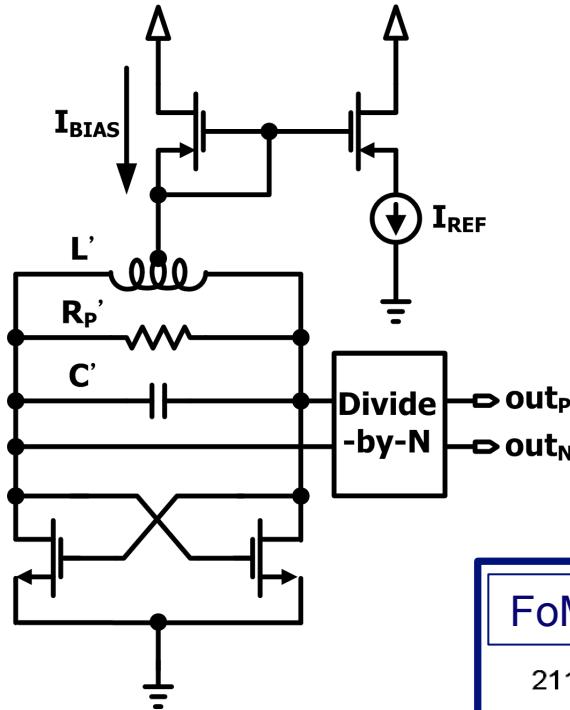
Use **Digital
Gates** to
Improve
Analog/RF
Performance

Use f_T for VCO Area Scaling

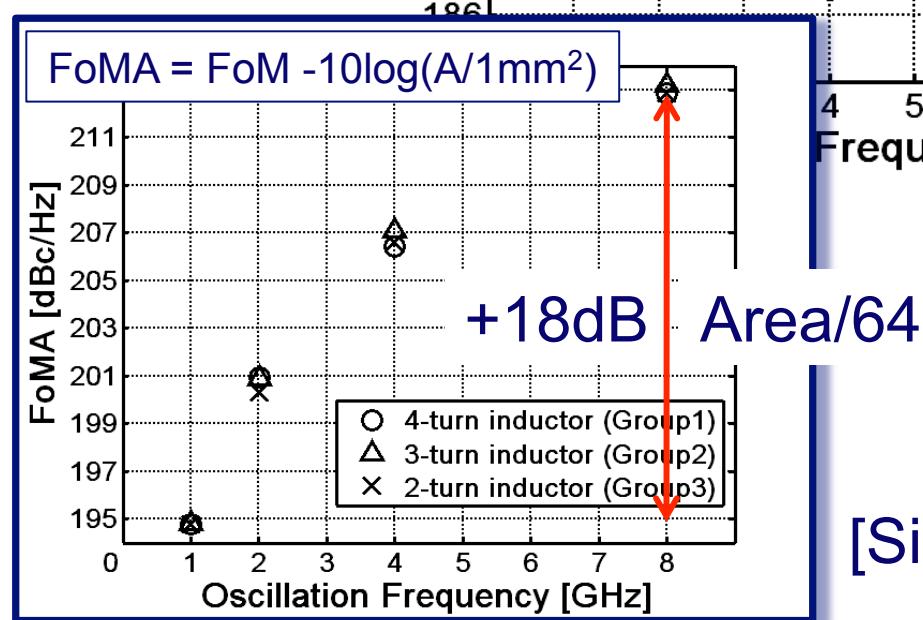
- Scaled CMOS → higher f_T
 - operate @ $N \times$ higher frequency
 - divide by N



VCO Area Scaling

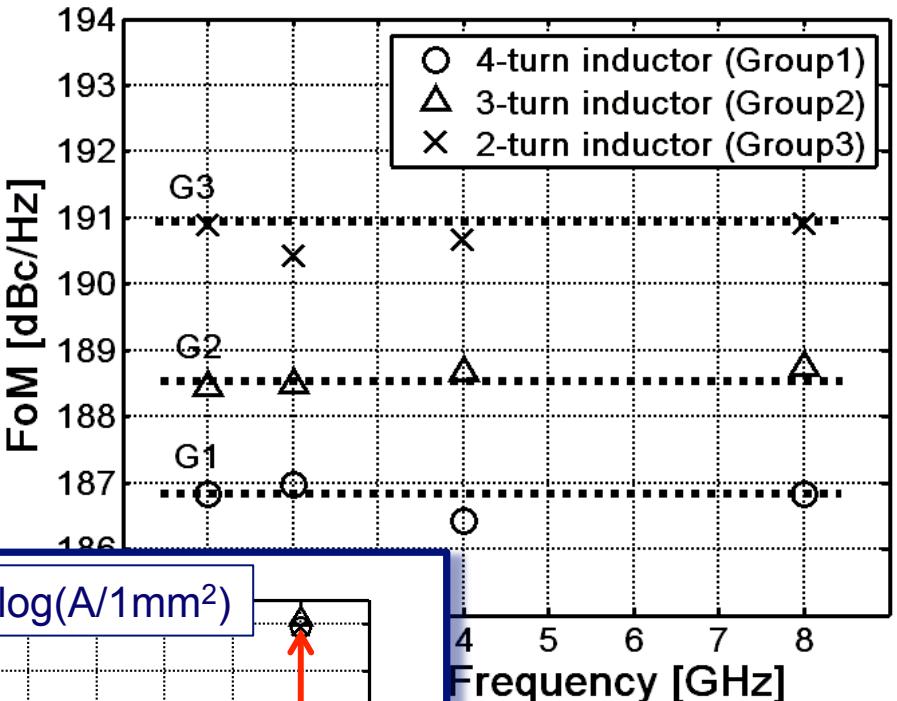


[Yu, Kinget,
TCASII 09]

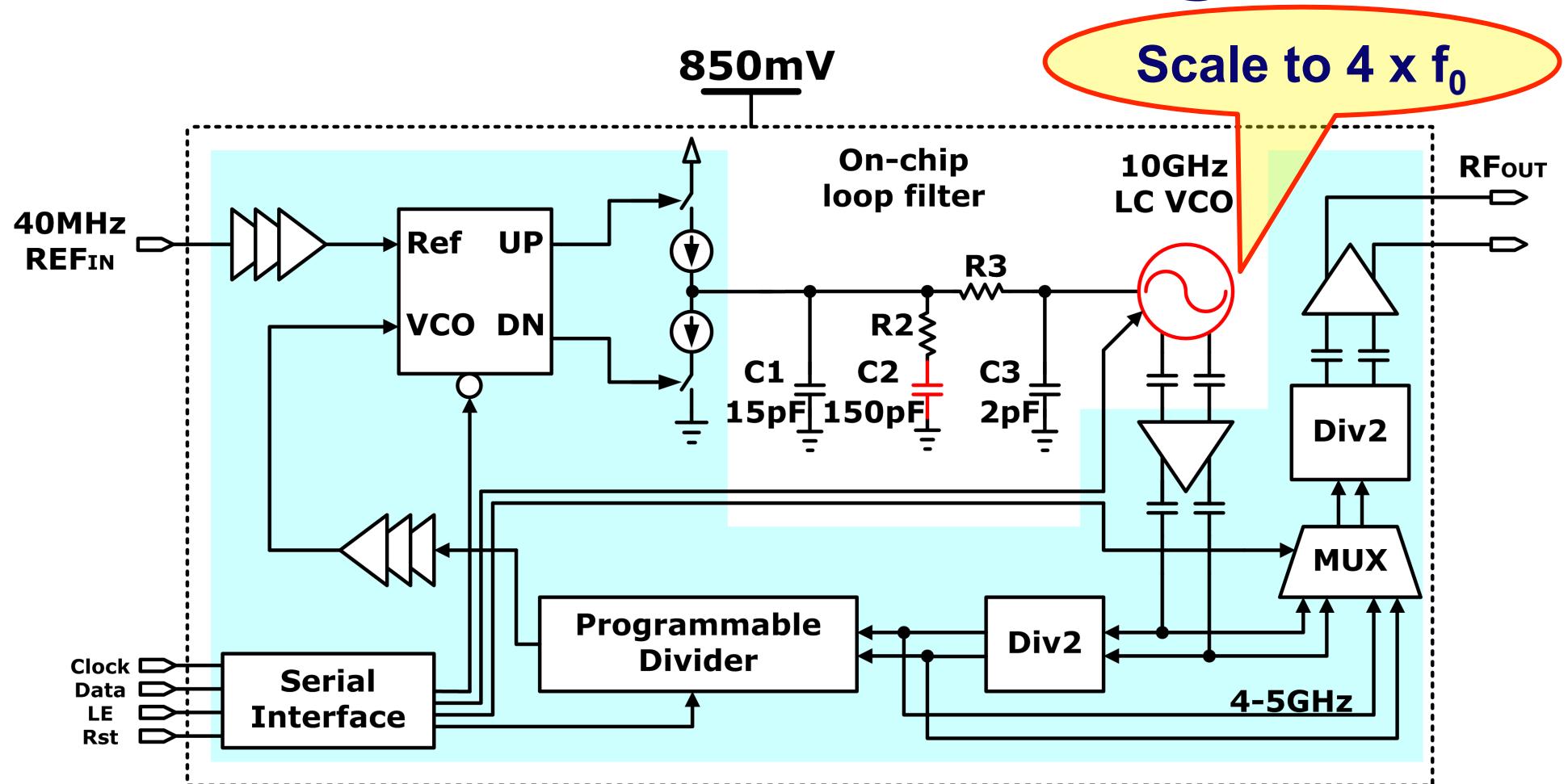


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[Sim. in 45nm]



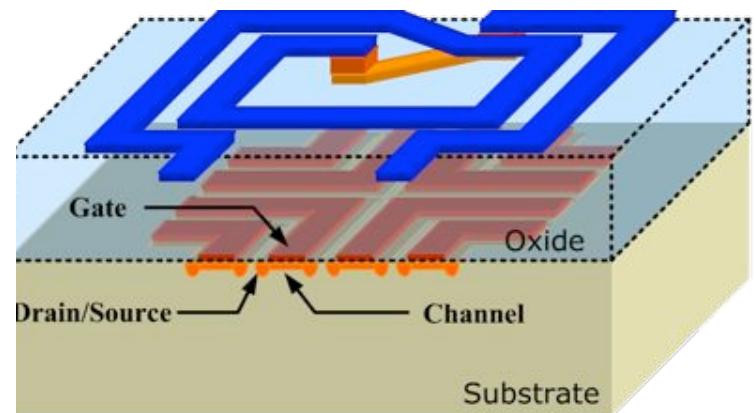
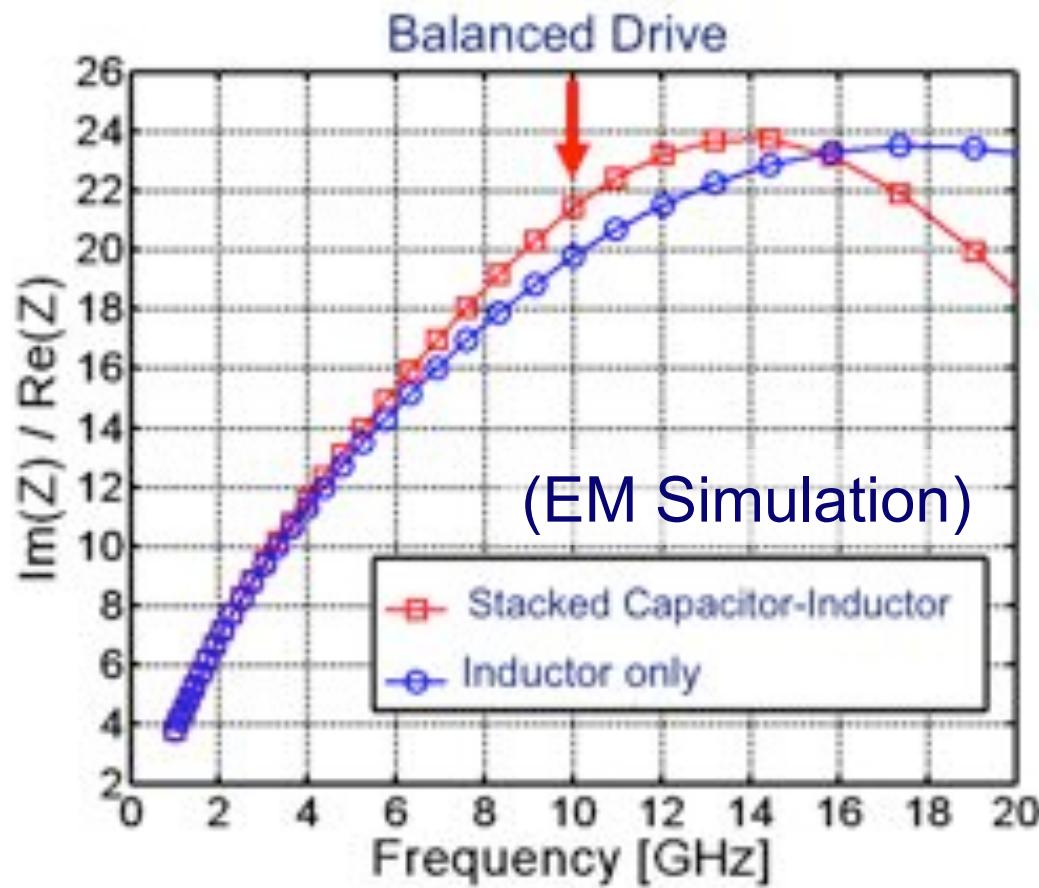
PLL and Area Scaling



Circuits that scale easily with feature size

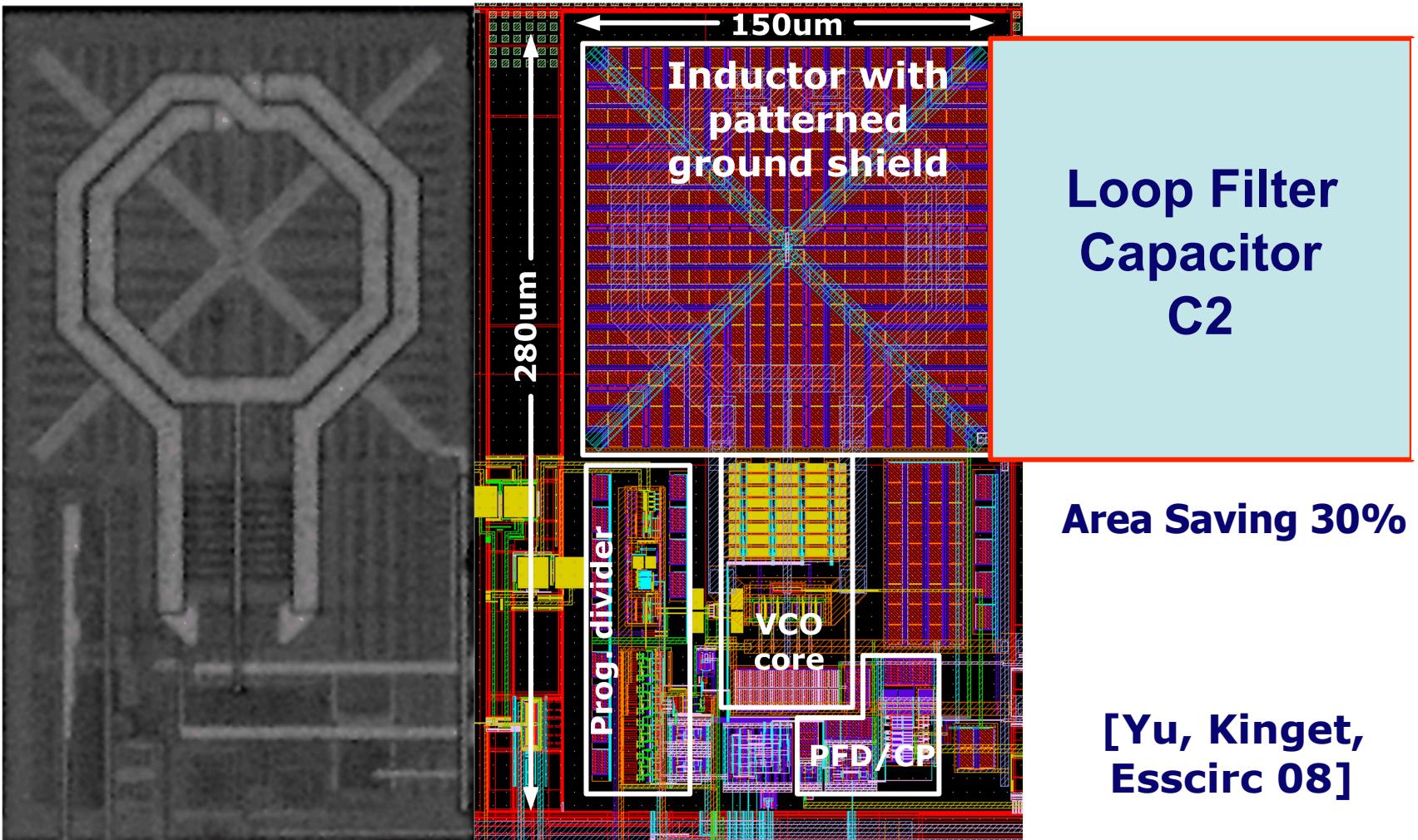
- 150pF needs $\sim 13000\text{um}^2$ of inversion-mode MOS capacitor

Stacked MOS Cap-Inductor



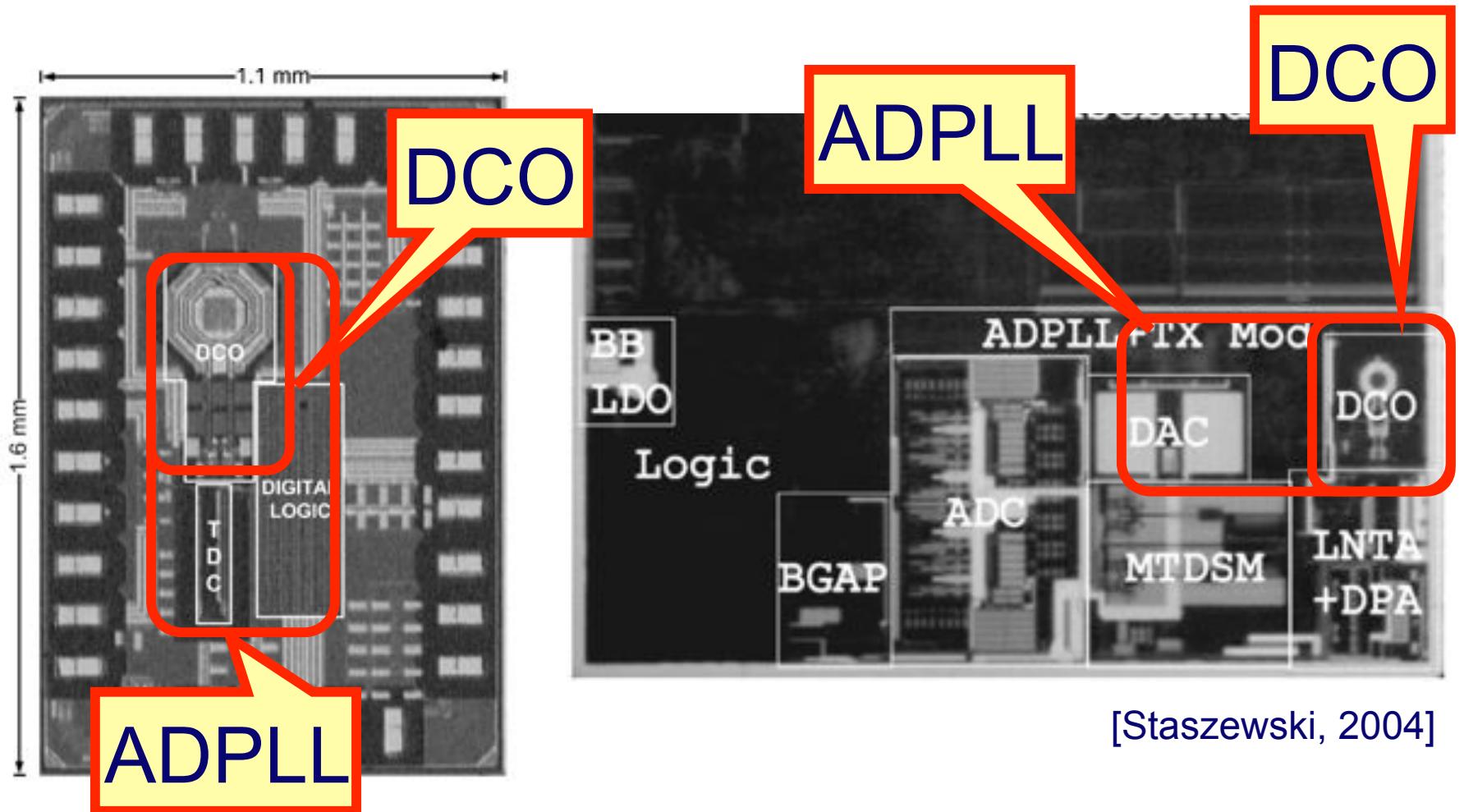
→ no Q degradation, even improvement (shielding)

0.042mm² Fully Int. PLL



Fully Integrated PLL, on-chip loop filter under VCO inductor
45nm LP CMOS; $V_{DD}=0.85V$; 10GHz VCO; 2.5GHz o/p

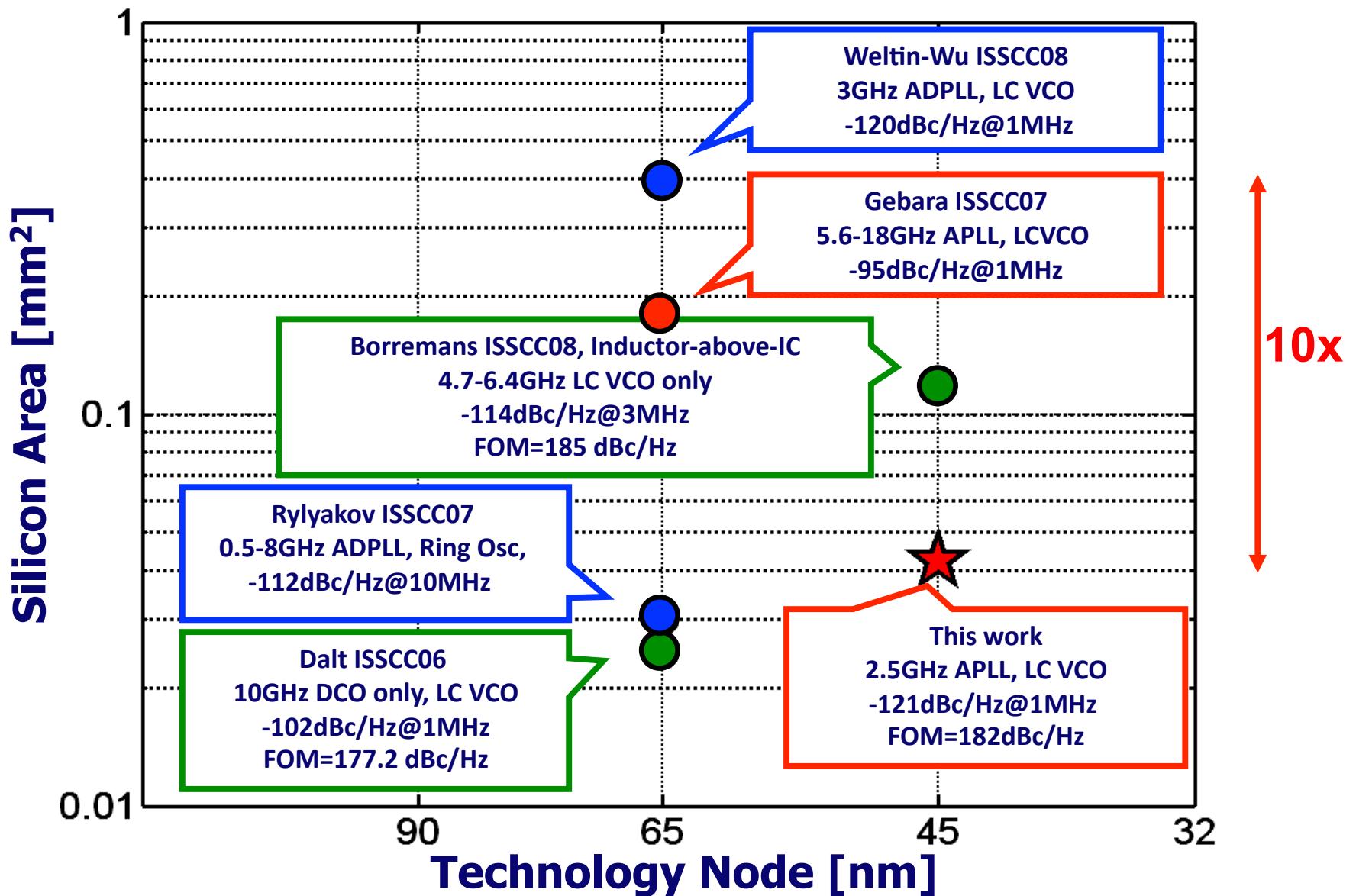
All-Digital PLLs



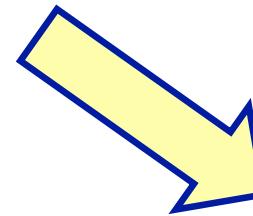
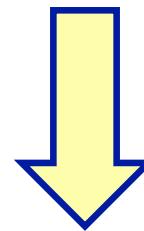
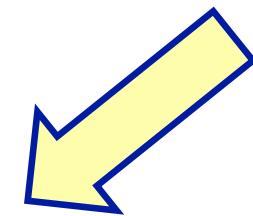
[Staszewski, 2004]

[Weltin-Wu, 2008]

Area & Performance Comparison



Design Techniques to Keep Analog & RF Compatible with Nanoscale CMOS

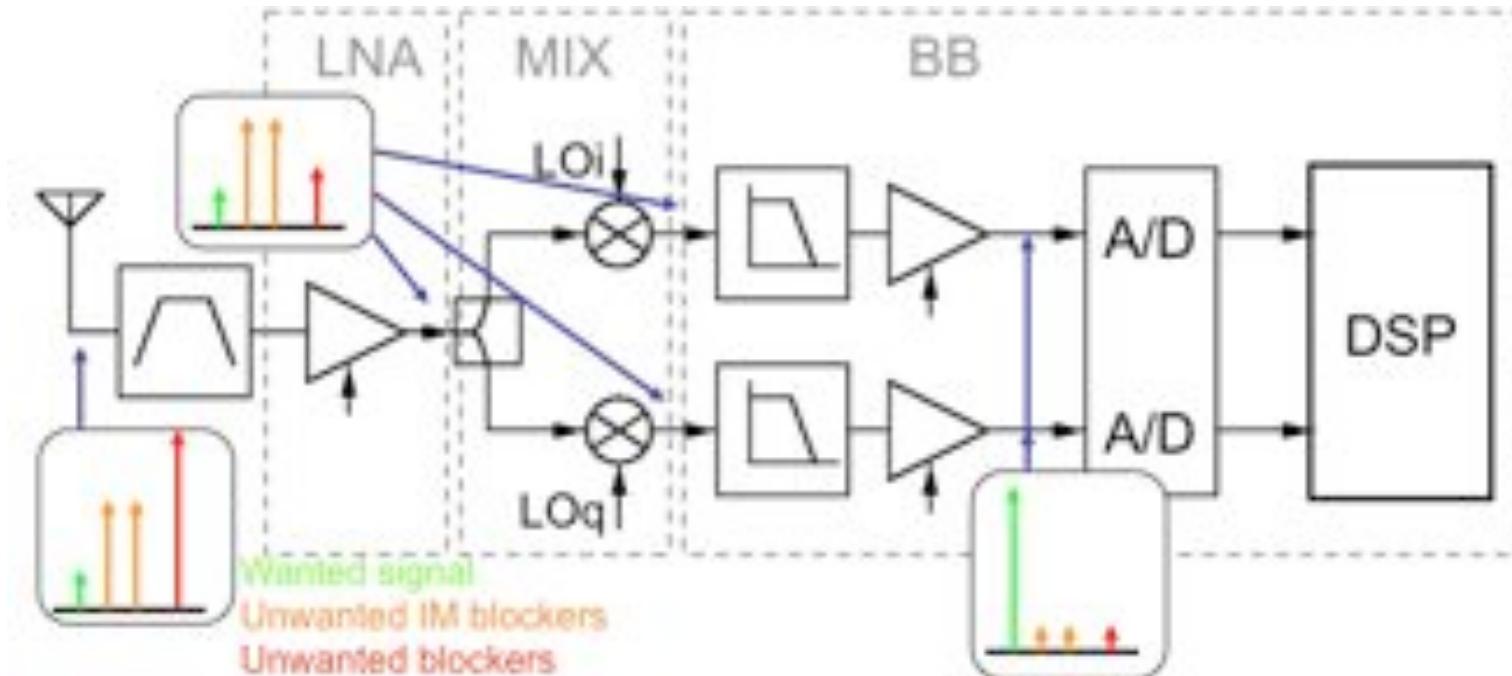


Scale the
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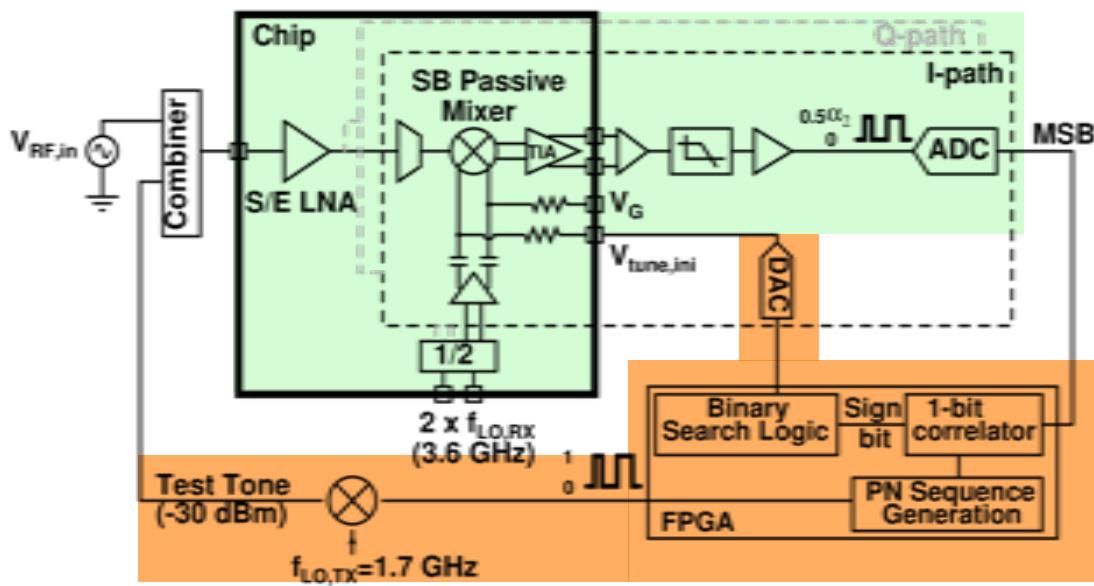
Use Digital Gates In RF... How?



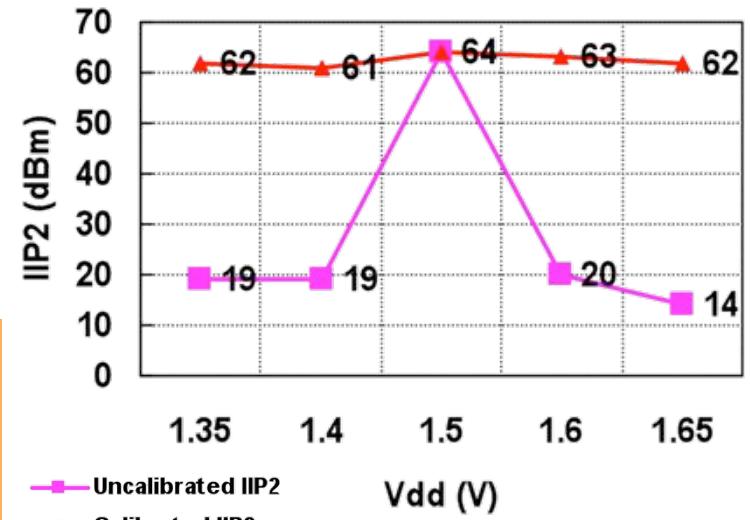
- For RF, improvement of linearity using digital gates has many opportunities
 - The signals generating the errors are *out-of-band interferers*, which do not reach the baseband...
 - In contrast to mixed signal digital assistance we need to **address problem in the front-end for RF!**
- Use digital assistance to self-calibrate RF front-end

Digital Self-Calibration of RCV IIP2

Block Diagram



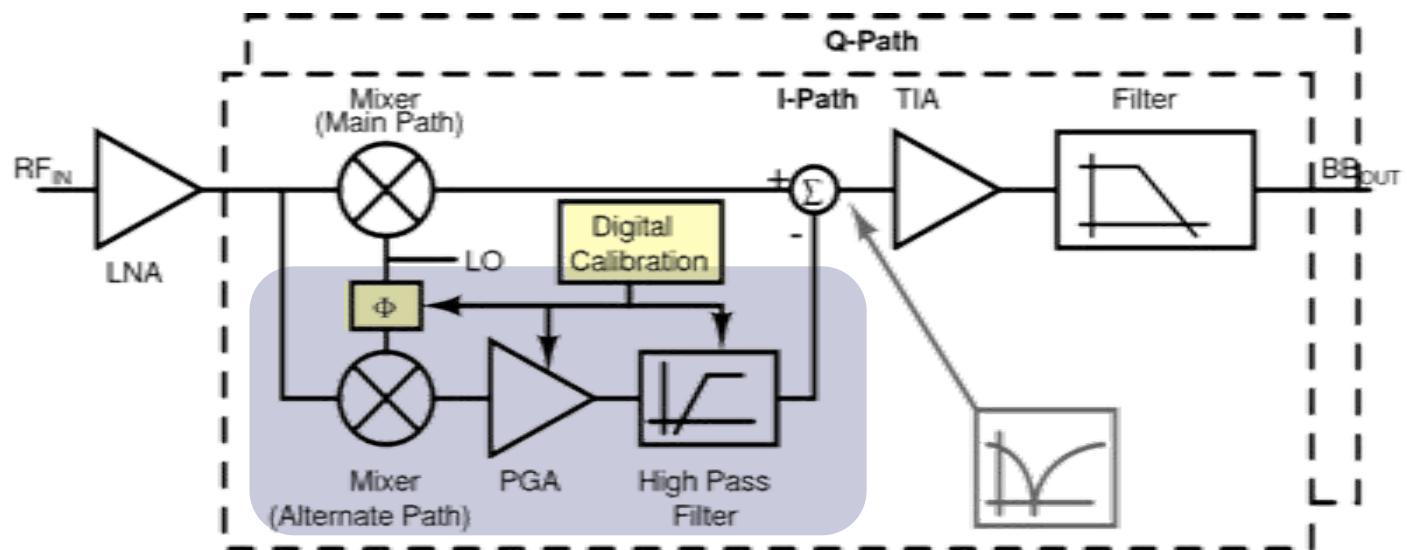
Measured Results Receiver



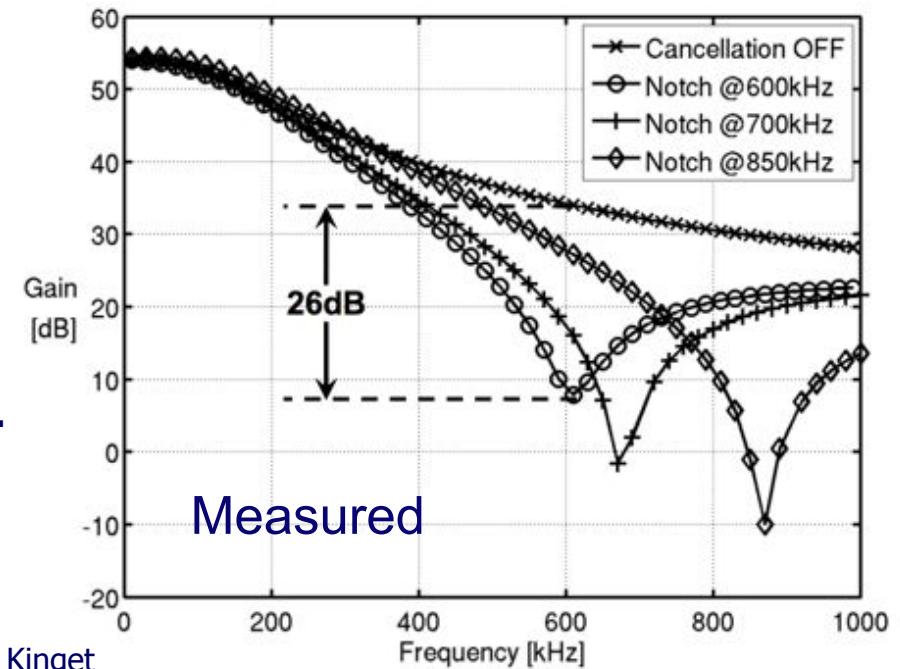
[ISSCC 2010]

- >40dB IIP2 improvement!
- Performance very stable w.r.t. any changes (VDD, freq., ...)
- *Simpler, lower power RF circuits* can be used taking advantage of calibration engine
- Low Power, no extra power consumption for RF operation!

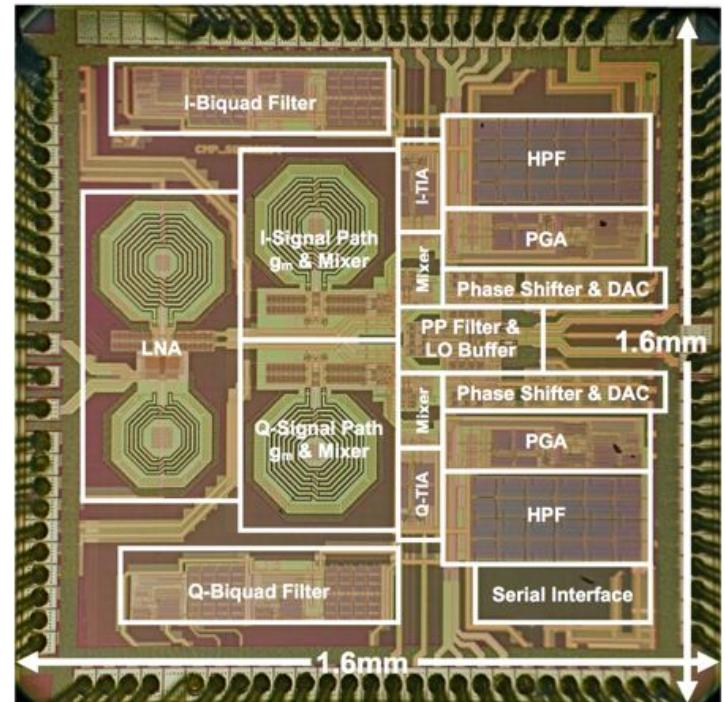
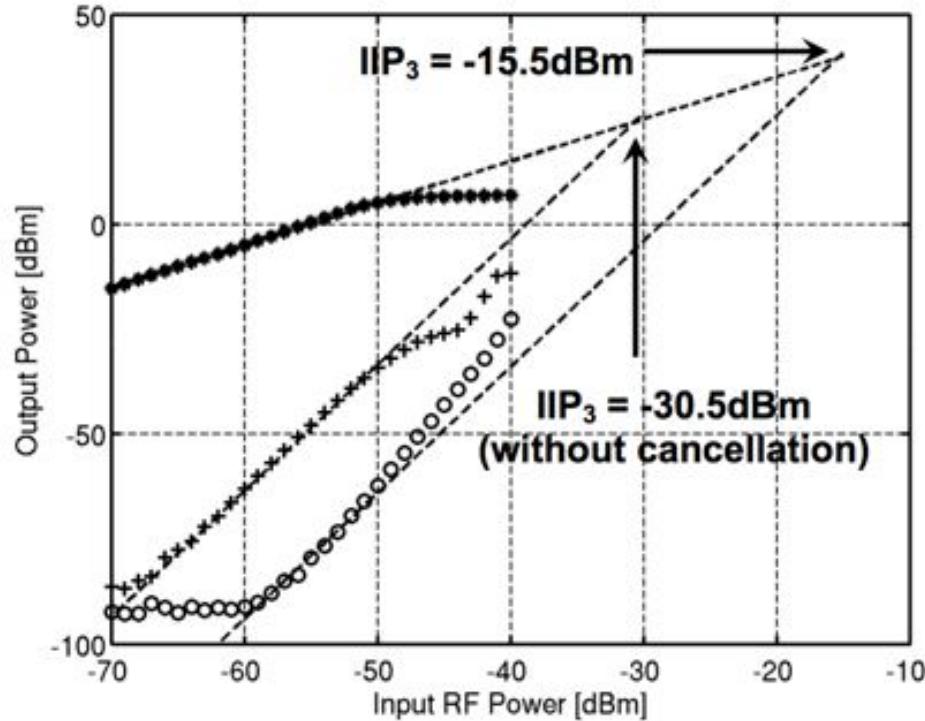
ULV RCV with FF In-band Interf. Cancel.



- Front-end **Interferer Cancellation** significantly reduces baseband linearity requirements resulting in a significant performance improvement
- >20dB of attenuation for out of channel blockers
- Digital calibration of LO phase (Φ) and alt. path gain is **key enabler** to automatically tune the position of the cancellation notch



0.6V GSM Receiver

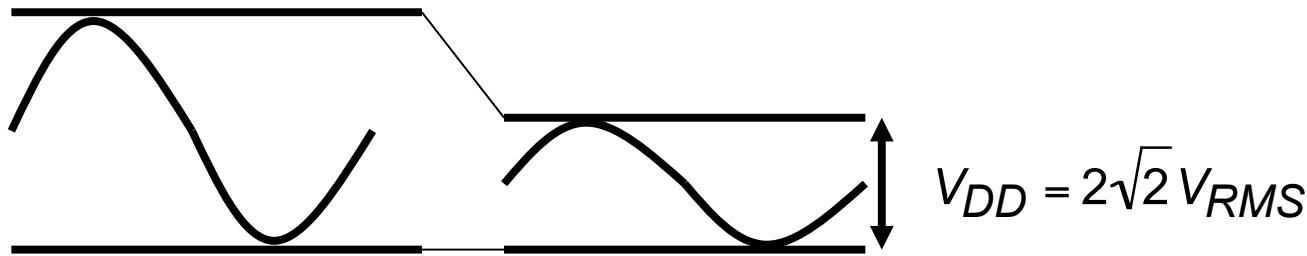


[VLSI, 2010]

- 55dB Gain, 6dB NF, -15.5dBm IIP₃,
- 21mW @ 0.6V (LNA, Mixers, Cancellers, Baseband, LO Buffers)
- 65nm CMOS

Review & Outlook

Fundamentals: Power Limits



- Noise limited circuits [Vittoz90]:

$$SNR = \frac{V_{RMS}}{\sqrt{v_{n,RMS}^2}} \quad v_{n,RMS}^2 = \frac{kT}{C} \quad I_{DC} = 2fC\sqrt{2}V_{RMS}$$

$$P \geq 8 kT f SNR^2$$

ideal class B

- Mismatch limited circuits [Kinget96]:

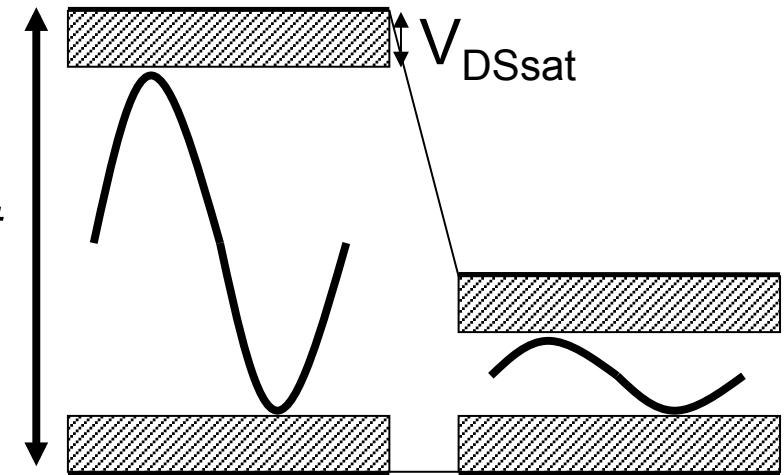
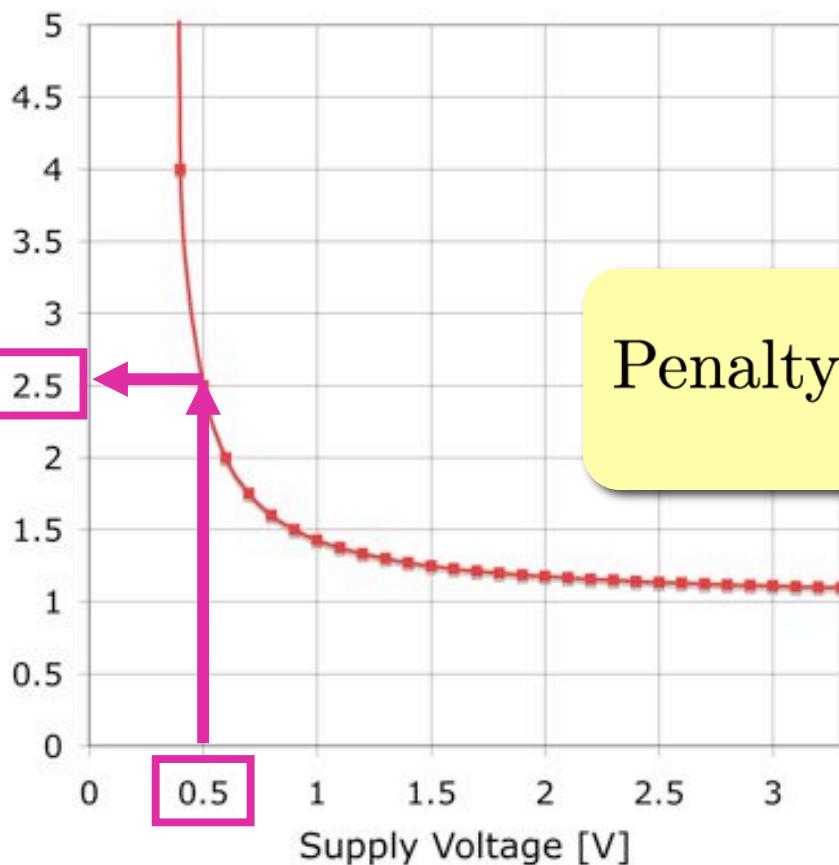
$$Acc = \frac{V_{RMS}}{3\sigma(V_{OS})} \quad \sigma^2(V_{OS}) = \frac{C_{ox} A_{VT}^2}{C} \quad I_{DC} = 2fC\sqrt{2}V_{RMS}$$

$$P \geq 24 C_{ox} A_{VT}^2 f Acc^2$$

Low Voltage Power Penalty

- Finite V_{DSsat} :

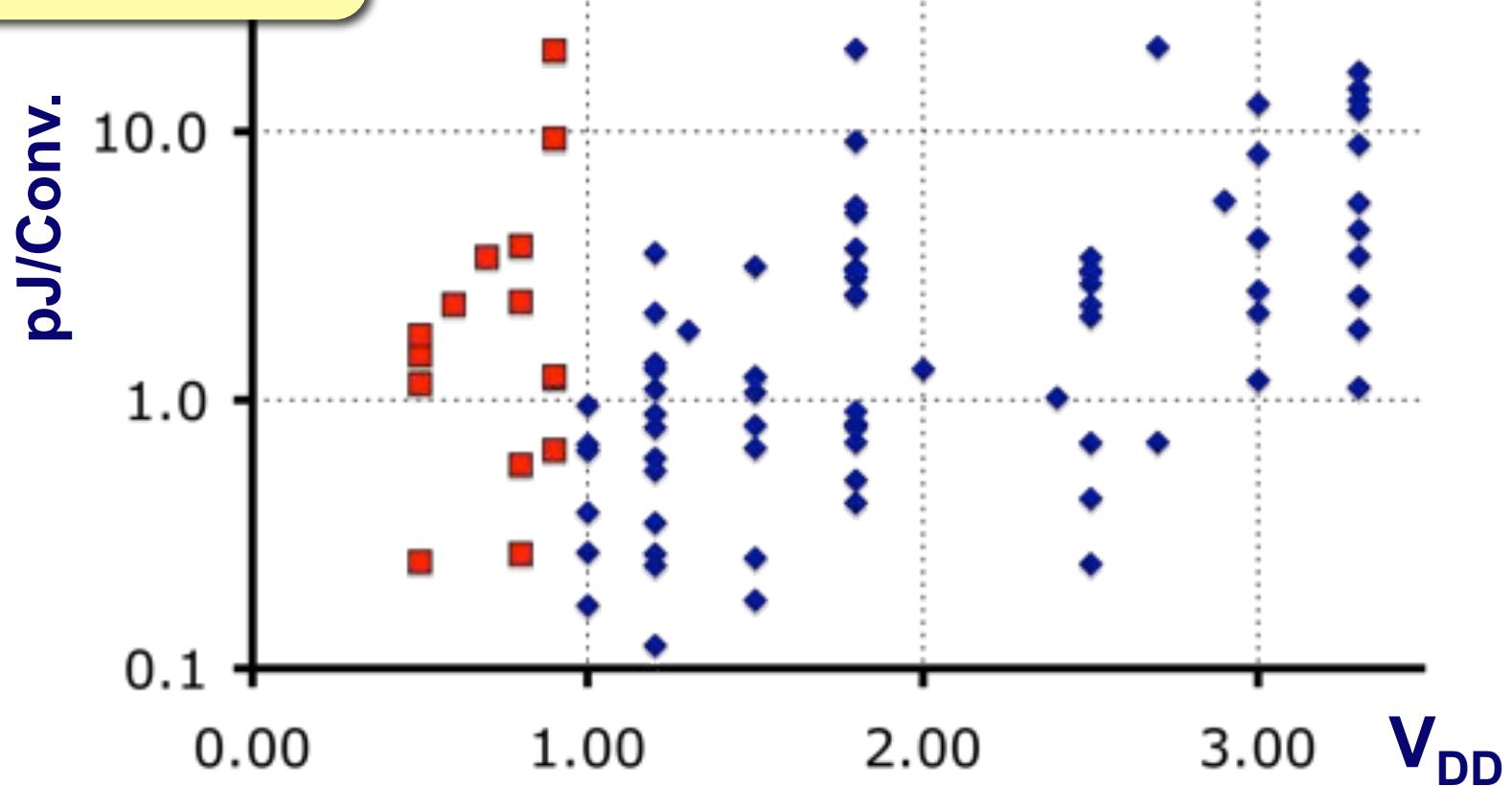
$$V_{DD} = 2\sqrt{2} V_{RMS} + 2V_{DSsat}$$



$$\text{PenaltyFactor} = 1 + \frac{2V_{DS,sat}}{V_{DD} - 2V_{DS,sat}}$$

ADC FOM vs V_{DD}

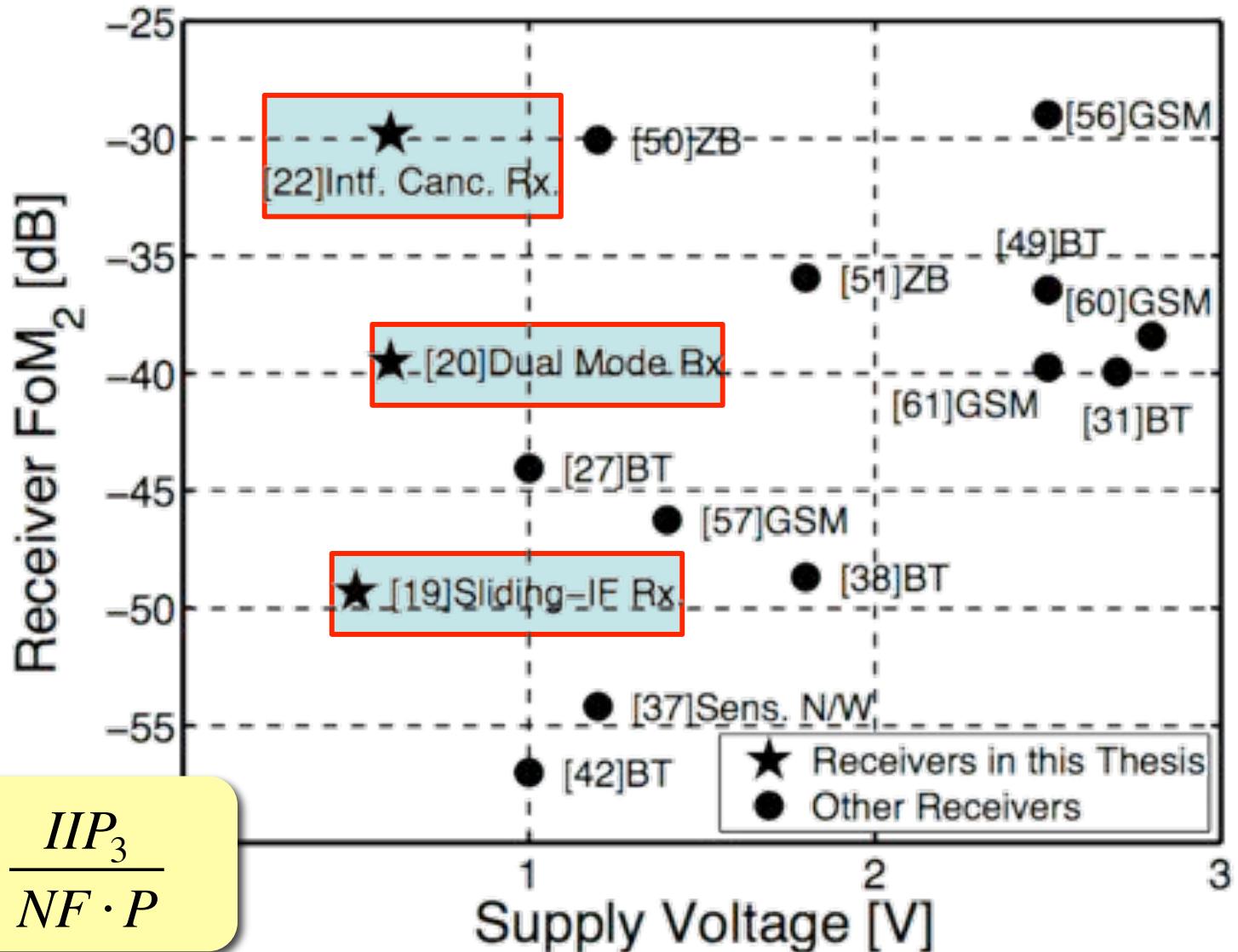
$$\text{FOM} = \frac{P}{\frac{SNDR - 1.76}{6.02} \cdot 2 \cdot BW \cdot 2}$$



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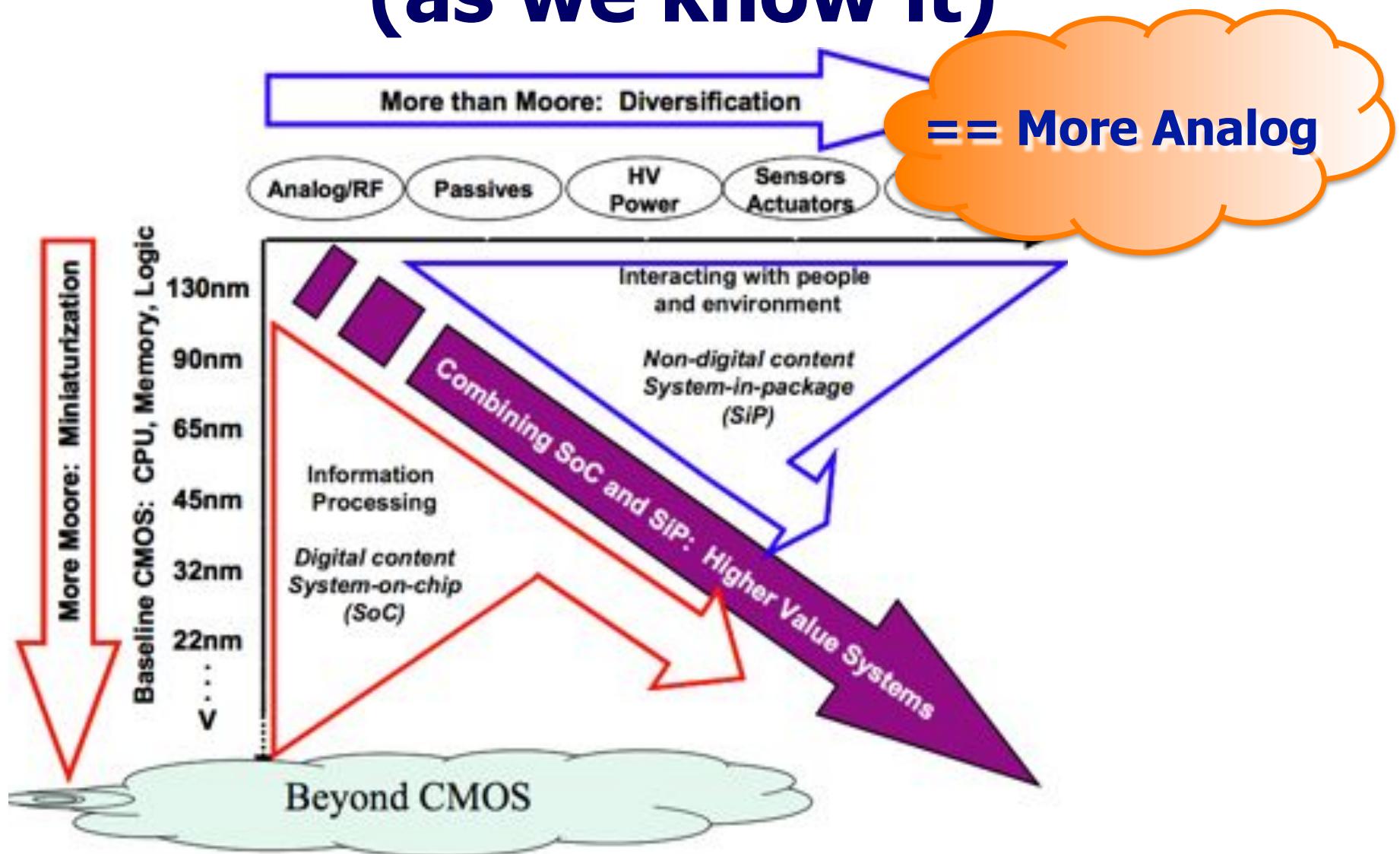
Most data taken from B. Murmann,
“A/D Converter ISSCC Performance Data”

Receiver FOM vs V_{DD}

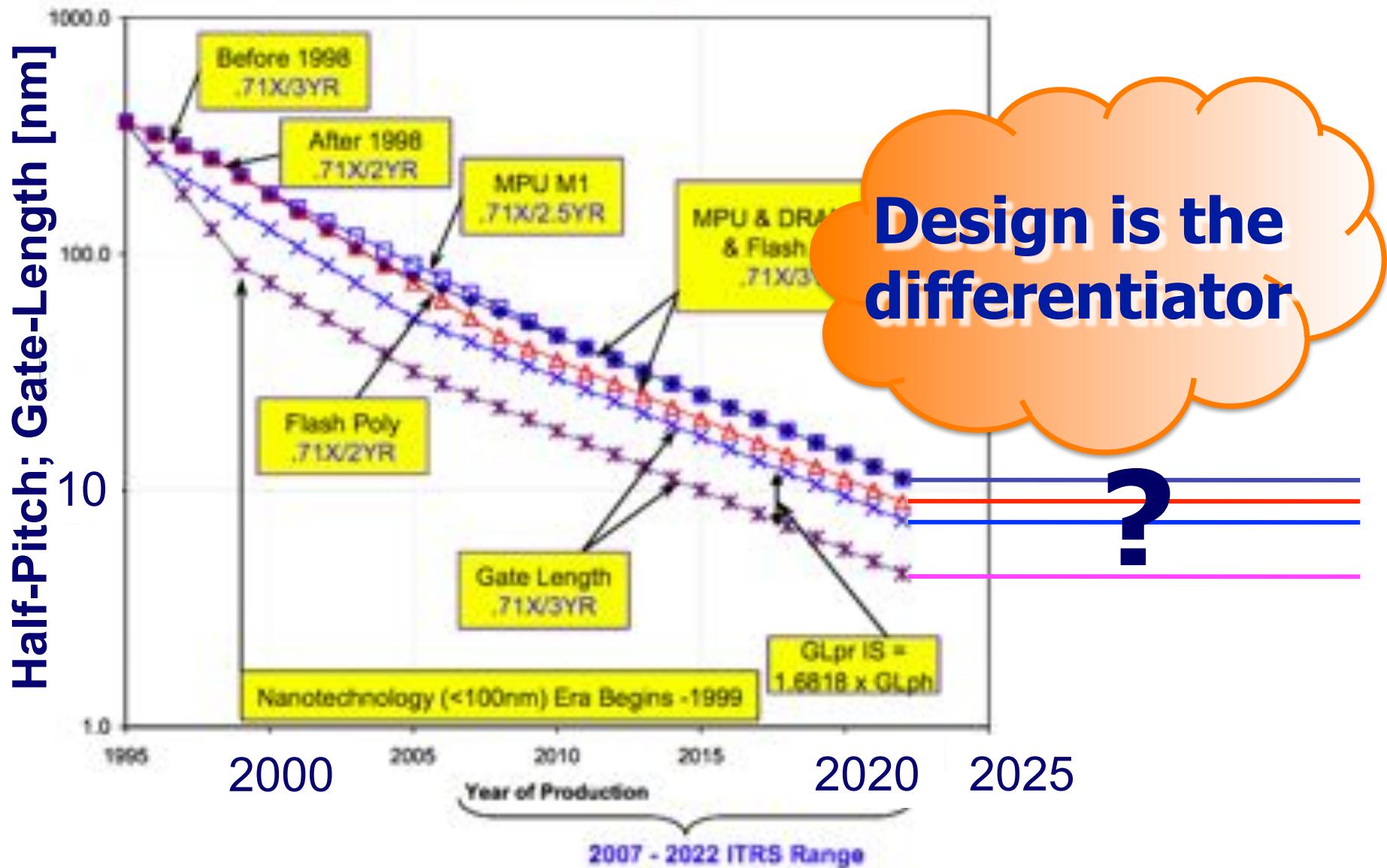


$$FOM_2 = \frac{IIP_3}{NF \cdot P}$$

End of Moore's Law...? (as we know it)



ITRS 2007-2022 – After Moore?



Conclusions

- Scaling is driving semiconductor technology and will continue for another decade, but with significant design challenges.
- Future Analog/RF in nanoscale CMOS
 - Reduce supply voltage
 - Reduce area
 - Exploit digital gates
- Design is becoming a prime differentiator

Plenty of open opportunities!!

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